

# SAMSUNG SSD PM1733a

Specification(PCIe® NVMe™ 2.5")

## Datasheet

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## Revision History

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Part Number	Capacity <sup>1)</sup>	LBA (512 Bytes size)
MZWLR1T9HCJR-00A07	1.92TB	3,750,748,848
MZWLR3T8HCLS-00A07	3.84TB	7,501,476,528
MZWLR7T6HBLA-00A07	7.68TB	15,002,931,888
MZWLR15THBLA-00A07	15.36TB	30,001,856,512
MZWLR30THBLA-00A07	30.72TB	60,001,615,872

**NAND**

- V6 256/512Gb NAND Flash Memory

**FEATURES**

- PCI Express Gen.3 /Gen.4
- Single port x4 lanes/Dual port x2 lanes
- Enhanced Power-Loss Data Protection
- LDPC ECC
- End-to-End Data Protection
- Support up to 128 I/O Queues per Port
- Support Deallocate (a.k.a. TRIM) Command
- Support PCI Express AER (Advanced Error Reporting)
- Support 129 vectors for MSI-X
- Support SSD Enhanced S.M.A.R.T. Feature Set
- Hardware based AES-XTS 256-bit Encryption Engine
- Static and Dynamic Wear Leveling
- Support SFF-8639 SMBus
- Support Hot Plug/Removal
- Support NVMe-MI basic
- Support Sanitize

**DRIVE CONFIGURATION**

- Form Factor SFF-8639 2.5-inch
- Interface PCI Express Gen.3 /Gen.4 1x4 2x2
- Bytes per Sector 512, 520, 4096, 4104, 4160 Bytes

**PERFORMANCE SPECIFICATIONS****(1) Gen.4**

- Data Transfer Rate<sup>2</sup> (128KB data size)
  - Sequential Read Up to 7,500 MB/s
  - Sequential Write 2TB : Up to 2,500 MB/s  
4/8/16/32TB : Up to 4,100 MB/s
- Data I/O Speed<sup>2</sup> (4KB data size, Sustained)
  - Random Read 2TB : Up to 1,400K IOPS  
4/8/16/32TB : Up to 1,600K IOPS
  - Random Write 2TB : Up to 100K IOPS  
4/8/16/32TB : Up to 170K IOPS
- Latency (Sustained random workload)
  - Read/Write (Typ.)<sup>3</sup> 100/25 us
  - Drive Ready Time (Typ.) Up to 4 sec
- Quality of service<sup>3</sup>
  - Read/Write (99%) 100/25 us

**COMPLIANCE**

- PCI Express Base Specification Rev. 4.0
- NVM Express Specification Rev. 1.3
- NVM Express Management Interface Specification Rev. 1.0a

**CERTIFICATIONS AND DECLARATIONS**

- c-UL-us, CE, TUV-GS, CB, BSMI, KC, VCCI, Morocco, RCM, FCC, IC

**PRODUCT ECOLOGICAL COMPLIANCE**

- RoHS meet spec

**RELIABILITY SPECIFICATIONS**

- Uncorrectable Bit Error Rate 1 sector per  $10^{17}$  bits read
- MTBF 2,000,000 hours
- Power on Cycles (Ambient) 20,000
- Component Design Life 5 years
- Endurance 1 DWPD
- TBW (@4KB Random Write)
  - 1.92TB 3.504 PB
  - 3.84TB 7.008 PB
  - 7.68TB 14.016 PB
  - 15.36TB 28.032 PB
  - 30.72TB 56.064 PB
- Data Retention 3 months

**ENVIRONMENTAL SPECIFICATIONS**

- Temperature, Case ( $T_C$ )<sup>4)</sup>
  - Operating 0 ~ 70 °C
  - Non-operating -40 ~ 85 °C
- Humidity (Non-operating) 5 ~ 95%
- Shock 1,500 G / 0.5msec
- Vibration
  - Sinusoidal 20 Gpeak, 10 ~ 2000Hz

**POWER REQUIREMENTS**

- Supply Voltage / Tolerance 12V±10%
- Active (Max. RMS) 21W
- Idle<sup>5</sup> (Typ.) 8 W / 5 W

**PHYSICAL DIMENSION**

- Width 69.85 ± 0.25 mm
- Length 100.20 ± 0.25 mm
- Height 15.00 + 0.00 / - 0.50 mm
- Weight Up to 190 g

**OPERATING SYSTEMS**

- Windows Server 2016 64-bit
- Windows Server 2019 64-bit
- Ubuntu 20.04 (Kernel 5.4)
- Ubuntu 18.10 (Kernel 4.18)
- CentOS 8.2 (Kernel 4.18.0-193)
- CentOS 7.6 (Kernel 3.10.0-957)

**NOTE: Specifications are subject to change without notice.**

- 1) 1TB =  $10^{12}$  Bytes, unformatted Capacity.  
User accessible capacity may vary depending on operating environment and formatting.
- 2) Based on PCI Express Gen3 x4, Random performance measured using FIO in CentOS 7.2 with queue depth 64 by 4 workers(Jobs) and Sequential performance with queue depth 128 by 1 worker. Actual performance may vary depending on use conditions and environment.
- 3) The read/write latency and Quality of Service are measured by using FIO in CentOS7.2 and 4KB transfer size with queue depth 1 on a random workload of sustained state.
- 4) Tc is measured at the hottest point on the case. Sufficient airflow is recommended to be operated properly on heavier workload within device operating temperature.
- 5) Normal idle mode / power-saving idle mode which is activated in case of no host command for 10 seconds (Typical)

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# 1.0 INTRODUCTION

## 1.1 General Description

This document describes the specifications of the Samsung SSD PM1733a, which is a native-PCIe SSD for enterprise application. The Samsung SSD PM1733a presents outstanding performance with instant responsiveness to the host system, by applying the Peripheral Component Interconnect Express (PCIe) 3.0 interface standard, as well as highly efficient Non-Volatile Memory Express (NVMe) Protocol.

The Samsung SSD PM1733a delivers wide bandwidth of 7,500MB/s for sequential read speed and 4,100B/s for sequential write speed under 21W power. By combining the enhanced reliability Samsung NAND Flash memory silicon with NAND Flash management technologies, the Samsung SSD PM1733a delivers the extended endurance of up to 1 Drive Writes Per Day (DWPD) for 5 years, which is suitable for enterprise applications, in one 2.5-inch form factor lineup: 1.92TB, 3.84TB, 7.68TB, 15.36TB, 30.72TB

In addition, the Samsung SSD PM1733a supports Hot Plug insertion and removal feature by employing the efficient circuitry for Power Loss Protection (PLP) and handling inrush current. PLP solution can guarantee that data issued by the host system are written to the storage media without any loss in the event of sudden power off or sudden power failure. Inrush current handler can protect the internal components from the electrical and physical damages.

## 1.2 Product List

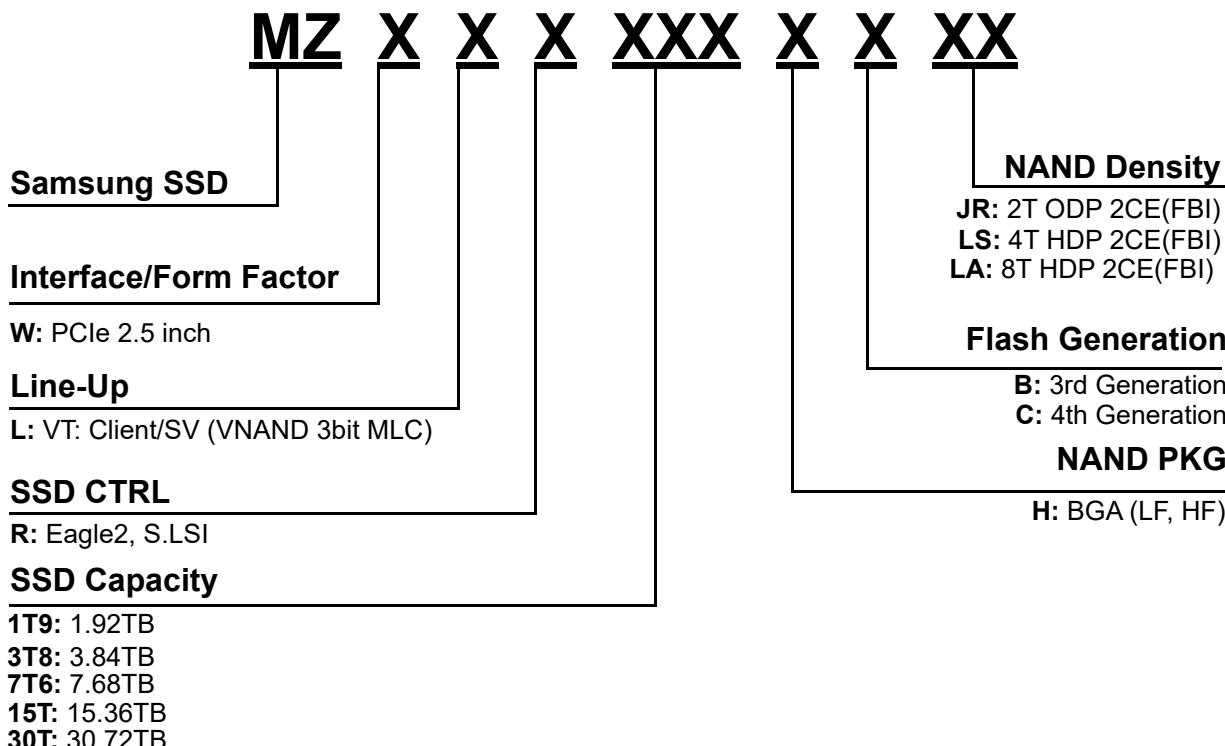
[Table 1] Product List

Type	Capacity	Part Number
2.5-inch <sup>1)</sup>	1.92TB	MZWLRLT9HCJR-00A07
	3.84TB	MZWLRL3T8HCLS-00A07
	7.68TB	MZWLRL7T6HBLA-00A07
	15.36TB	MZWLRL15THBLA-00A07
	30.72TB	MZWLRL30THBLA-00A07

NOTE:

1) SFF-8639 combo (SATA, SAS, PCIe) standard connector

## 1.3 Ordering Information



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## 2.0 PRODUCT SPECIFICATIONS

### 2.1 Capacity

[Table 2] User Capacity and Addressable Sectors

Capacity <sup>2)</sup>	Max LBA <sup>3)</sup>
1.92TB	3,750,748,847
3.84TB	7,501,476,527
7.68TB	15,002,931,887
15.36TB	30,001,856,511
30.72TB	60,001,615,871

**NOTE:**1) 1TB =  $10^{12}$  Bytes, 1 Sector = 512Bytes

2) Capacity shown in Table 2 represents the total usable capacity of the SSD which may be less than the total physical capacity. A certain area in physical capacity, not in the area shown to the user, might be used for the purpose of NAND flash management.

3) Max. LBA shown in Table 2 represents the total user addressable sectors in LBA mode and calculated by IDEMA.

### 2.2 Performance

[Table 3] Sustained Random Read/Write Performance (IOPS)

Maximum Performance <sup>1)</sup>		Unit	1.92TB	3.84TB	7.68TB	15.36TB	30.72TB
PCIe Gen.4	Random 4KB Read	IOPS	1400K	1600K	1600K	1600K	1600K
	Random 4KB Write	IOPS	100K	170K	170K	170K	170K

**NOTE:**

1) Random performance in Table 3 PCIe GEN4 was measured by using FIO in Ubuntu 17.10 with queue depth 64 by 16 workers(Jobs). Actual performance may vary depending on use conditions and environment.

[Table 4] Sequential Read/Write Performance

Maximum Performance <sup>1)</sup>		Unit	1.92TB	3.84TB	7.68TB	15.36TB	30.72TB
PCIe Gen.4	Sequential 128KB Read	MB/s	7,500	7,500	7,500	7,500	7,500
	Sequential 128KB Write	MB/s	2,500	4,100	4,100	4,100	4,100

**NOTE:**

1) Sequential performance in Table 4 PCIe GEN4 was measured by using FIO in Ubuntu 17.10 with queue depth 64 by 1 worker(Job). Actual performance may vary depending on use conditions and environment.

### 2.3 Latency

[Table 5] Latency<sup>1</sup> (sustained state)

Queue Depth = 1		Unit	1.92TB	3.84TB	7.68TB	15.36TB	30.72TB
PCIe Gen.4	4KB Random Read/Write <sup>2</sup>	us	100/25	100/25	100/25	100/25	100/25
	Sequential Read/Write <sup>3</sup>	us	270/100	270/100	270/100	270/100	270/100
Drive Ready Time <sup>4</sup>		sec	4	4	4	4	4

**NOTE:**

1) Typical values.

2) The random read/write latency is measured by using FIO in Ubuntu 17.10 and 4KB transfer size with queue depth 1 on a random workload of sustained state.

3) The sequential read/write latency is measured by using FIO in Ubuntu 17.10 and 128KB transfer size with queue depth 1 on a sequential workload of sustained state.

4) The maximum taking time to be ready for receiving commands after power-up (CSTS.Ready=1). It is expected that I/O commands may not be completed at this point.

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## 2.4 Quality of Service (QoS)

[Table 6] Quality of Service (QoS)

Quality of Service (99%)		Unit	1.92TB	3.84TB	7.68TB	15.36TB	30.72TB
PCIe Gen.4	Read(4KB)(QD=1,Job=1)	us	100	100	100	100	100
	Write(4KB)(QD=1,Job=1)	us	25	25	25	25	25
	Read(4KB)(QD=64,Job=4)	ms	1	1	1	1	1
	Write(4KB)(QD=64,Job=4)	ms	7	7	7	7	7
Quality of Service (99.99%)		Unit	1.92TB	3.84TB	7.68TB	15.36TB	30.72TB
PCIe Gen.4	Read(4KB)(QD=1,Job=1)	us	140	140	140	140	140
	Write(4KB)(QD=1,Job=1)	us	100	100	100	100	100
	Read(4KB)(QD=64,Job=4)	ms	2	2	2	2	2
	Write(4KB)(QD=64,Job=4)	ms	10	10	10	10	10

**NOTE:**  
 1) QoS is measured using FIO (99/99.99 %) with queue depth 1, Job=1 on single port and queue depth 64, Job=4 for single port on 4KB random and write.  
 2) QoS is measured as the maximum round-trip time taken for 99 % of commands to host.  
 3) QoS is measured as the maximum round-trip time taken for 99.99 % of commands to host.

## 2.5 IOPS Consistency

[Table 7] IOPS Consistency

IOPS Consistency1, 2	Unit	1.92TB	3.84TB	7.68TB	15.36TB	30.72TB
Random Read (4 KB)	%	95	95	95	95	95
Random Write (4 KB)	%	90	90	90	90	90
Random Read (8 KB)	%	95	95	95	95	95
Random Write (8 KB)	%	90	90	90	90	88

**NOTE:**  
 1) IOPS consistency measured using FIO with queue depth 128, worker 4.  
 2) IOPS Consistency (%) = (IOPS in the 99.9% slowest 1-second interval)/(average IOPS during the test).

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## 2.6 Power

The Samsung SSD PM1733a is implemented in standardized 2.5-inch form factor and gets primary 12V power as well as auxiliary 3.3V (3.3Vaux) power through the indicated pins (#P13~#P15 for 12V and #E3 for 3.3Vaux in SFF-8639 connector plug) from the host system.

For 12V and 3.3Vaux, the allowable voltage tolerance and noise level in SSD are described in chapter 2.6.1, the power consumption in chapter 2.6.2 and the inrush current in chapter 2.8.2.

### 2.6.1 Maximum Voltage Ratings (12V and 3.3Vaux)

[Table 8] Allowable Voltage Tolerance<sup>1)</sup>

Operating Voltage	1.92TB	3.84TB	7.68TB	15.36TB	30.72TB
12V <sup>2</sup>			±10%		
12V Rise time (Max/Min)			50ms/1ms		
12V Fall time (Max/Min) <sup>4</sup>			5s/1ms		
12V Noise level			350 mV pp 10Hz – 220 MHz		
Minimum Off Time			10ms		
3.3Vaux <sup>3</sup>			±10%		
3.3Vaux Rise time (Max/Min)			50ms/1ms		
3.3Vaux Fall time (Max/Min) <sup>4</sup>			5ms/1ms		
3.3Vaux Noise level			300 mV pp 10Hz – 100 KHz 50 mV pp 100KHz – 20 MHz		

**NOTE:**

- 1) The components inside SSD were designed to endure the range of voltage fluctuations, which might be induced by the host system, in Table 8.
- 2) For 12V operating voltage, the minimum allowable is 10.8V and the maximum 13.2V.
- 3) For 3.3Vaux, the minimum allowable voltage is 2.97V and the maximum 3.63V.
- 4) Fall time needs to be equal or better than minimum in order to guarantee full functionality of enhanced power loss management.

### 2.6.2 Power Consumption (12V)

In enterprise server and storage system, the Samsung SSD PM1733a is designed for the specific usage, which means that SSD will be always operated by the host system during the entire life. Hence, the Samsung SSD PM1733a does not manage any low power modes except for the Active/Idle, Off mode.

[Table 9] Power Consumption (12V Supply Voltage)<sup>1)</sup>

Power Mode		1.92TB	3.84TB	7.68TB	15.36TB	30.72TB
PCIe Gen.4	Active <sup>2</sup>	Read	15.5W	17.5W	18W	19W
		Write	14.5W	19W	19W	20.5W
	Idle <sup>3</sup>		7.5W / 4.5W	7.5W / 4.5W	7.5W / 4.5W	7.5W / 4.5W
	Off	0W	0W	0W	0W	0W

**NOTE:**

- 1) Power consumption was measured in the 12V power pins (#P13~#P15) of the connector plug in SSD. The active and idle power is defined as the highest averaged power value, which is the maximum RMS average value over 100 ms duration.
  - 2) The measurement condition for active power is assumed for maximum power between sequential or random performance.
  - 3) The idle state is defined as the state that the host system can issue any commands into SSD at any time.
- Normal idle mode / power-saving idle mode which is activated in case of no host command for 10 seconds (Typical)

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## 2.7 Reliability

The reliability specification of the Samsung SSD PM1733a follows JEDEC standard, which are included in JESD218A and JESD219A documents.

### 2.7.1 Mean Time Between Failures

By definition, Mean Time between Failures (MTBF) is the estimated time between failures occurring during SSD operation.

[Table 10] MTBF Specifications

Parameter	1.92TB	3.84TB	7.68TB	15.36TB	30.72TB
MTBF				2,000,000 Hours	

### 2.7.2 Uncorrectable Bit Error Rate

By definition, Uncorrectable Bit Error Rate (UBER) is a metric for the rate of occurrence of data errors, equal to the number of data errors per bits read as specified in the JESD218 document of JEDEC standard.

[Table 11] UBER Specifications

Parameter	1.92TB	3.84TB	7.68TB	15.36TB	30.72TB
UBER				1 sector per $10^{17}$ bits read	

NOTE:

1) For the enterprise application, JEDEC recommends that UBER shall be below  $10^{-16}$

### 2.7.3 Data Retention

By definition, data retention is the expected time period for retaining data in the SSD at the maximum rated endurance in power-off state as specified in the JESD218 document of JEDEC standard.

[Table 12] Data Retention

Parameter	1.92TB	3.84TB	7.68TB	15.36TB	30.72TB
Data Retention <sup>1</sup>				3 months	

NOTE:

1) Data retention was measured by assuming that SSD reaches the maximum rated endurance at 40°C in power-off state.

### 2.7.4 Endurance

By definition, the endurance of SSD in enterprise application is defined as the maximum number of drive writes per day that can meet the requirements specified in the JESD218 document of JEDEC standard.

[Table 13] Drive Write Per Day (DWPD)

Parameter	1.92TB	3.84TB	7.68TB	15.36TB	30.72TB
DWPD				1 drive writes per day over 5 years	

[Table 14] Petabyte Byte Written (PBW)

Parameter	Unit	1.92TB	3.84TB	7.68TB	15.36TB	30.72TB
TBW	PB	3.504	7.008	14.016	28.032	56.064

NOTE:

1) Relational formula between DWPD and PBW is like below:

$$\text{PBW} = \text{DWPD} \times 365 \times 5 \times \text{User capacity}$$

2) PBW was calculated at 4KB random write.

3) 1PB =  $10^{15}$  Bytes

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## 2.8 Protection Function

### 2.8.1 Power Loss Protection

By using internal back-up power technology, the Samsung SSD PM1733a supports power loss protection (PLP) feature to guarantee the reliability of data requested by the host system. When power is unpredictably lost, SSD can detect automatically this abnormal situation and transfer all user data and meta-data cached in DRAM into the Flash media during any SSD operations.

### 2.8.2 Inrush Current Protection

When the Samsung SSD PM1733a plugs in the backplane of host system, the significant amount of current is induced through 12V power rail. The Samsung SSD PM1733a has protection circuitry including a set of resistors and capacitors to alleviate the impact by inrush current through 12V power.

[Table 15] Inrush Current

Inrush Current	1.92TB	3.84TB	7.68TB	15.36TB	30.72TB
12 V				1.8A <sup>1)</sup>	

**NOTE:**

1) The measurement value of inrush current is also compatible with the standard specification of "Enterprise SSD Form Factor Version 1.0a" released by SSD Form Factor Working Group.

## 2.9 Environmental Specification

### 2.9.1 Temperature

[Table 16] Temperature, Case (Tc<sup>1</sup>)

	1.92TB	3.84TB	7.68TB	15.36TB	30.72TB
Temperature <sup>1)</sup>	Operating	0 to 70°C			
	Non-Operating <sup>2)</sup>	-40 to 85°C			

**NOTE:**

1) Tc is measured at the hottest point on the case. Sufficient airflow is recommended to be operated properly on heavier workload within device operating temperature.

2) Storing (or shipping) without power connection.

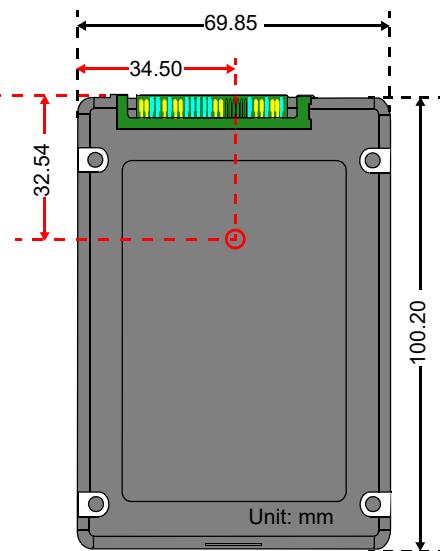


Figure 1. Tcase point (1.92TB, 3.84TB, 7.68TB)

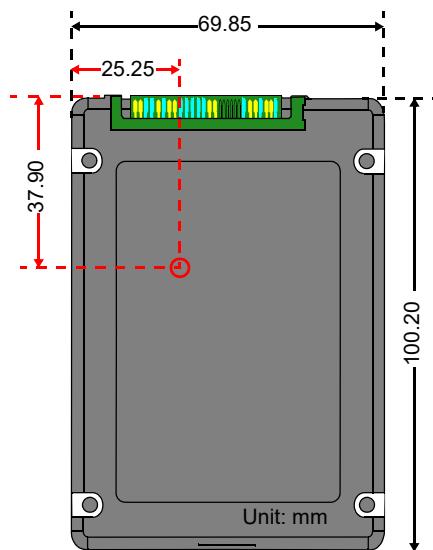


Figure 2. Tcase point (15.36, 30.72TB)

## 2.9.2 Dynamic Thermal Throttling

The dynamic thermal throttling (DTT) is implemented to prevent overheating. Table 17 shows the engaging and recovery temperature thresholds.

### 2.9.2.1 DTT Table

[Table 17] DTT Table

Step	1.92TB, 3.84TB, 7.68TB			15.36TB, 30.72TB		
	Engaging <sup>1)2)</sup>	Recovery	Performance <sup>3)</sup>	Engaging	Recovery	Performance
DTT1	80°C	79°C	<75%	76°C	75°C	<75%
DTT2	83°C	82°C	<40%	79°C	78°C	<40%
DTT3	85°C	84°C	<20%	81°C	80°C	<20%
Critical (DTT4)	87°C	86°C	0%	82°C	81°C	0%
Shut-down <sup>4)</sup>	93°C	n/a	n/a	92°C	n/a	n/a
Warning Composite Temperature (WCTEMP)	72°C			70°C		
Critical Composite Temperature (CCTEMP)	87°C			82°C		

NOTE:

- 1) All temperatures are based on  $T_{\text{composite}}$  values.
- 2) Recovering to the previous step as the temperature falls.
- 3) Throttling levels could be varying with workloads.
- 4) Hanged/Halted. Recovering after power cycle.

### 2.9.2.2 Composite temperature ( $T_{\text{composite}}$ )

The  $T_{\text{composite}}$  is defined by the correlation equations as the below.

$$T_{\text{composite}} = TS$$

where, TS means the temperature of reading in the thermal sensor on SSD.

## 2.9.3 Humidity

[Table 18] Humidity

	1.92TB	3.84TB	7.68TB	15.36TB	30.72TB
Humidity <sup>1)</sup>	Non-operating		5% to 95%		

NOTE:

- 1) Humidity is measured in non-condensing state.

## 2.9.4 Shock and Vibration

[Table 19] Shock and Vibration

	1.92TB	3.84TB	7.68TB	15.36TB	30.72TB
Shock <sup>1</sup>	Non-operating		1,500G		
Vibration <sup>2</sup>	Non-operating		20 Gpeak (10~2,000Hz, Sweep sine)		

NOTE:

- 1) Shock specifications assume that SSD shall be mounted with screws when input vibration is applied. Vibration may be applied in 3 axes (x, y and z) with a half sine waveform of 0.5ms duration in non-operating condition.
- 2) Vibration specifications assume that SSD shall be mounted with screws when input vibration is applied.  
The input vibration may be applied in 3 axes (x, y and z) and 4min/cycle, 4cycle/axis on 3 axis.

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## 3.0 MECHANICAL SPECIFICATIONS

### 3.1 Physical Information

The physical case of the Samsung SSD PM1733a in 2.5-inch form factor follows the standardized dimensions defined by SSD Form Factor Work Group.

[Table 20] Physical Dimensions and Weight

Parameter	Unit	1.92TB	3.84TB	7.68TB	15.36TB	30.72TB
Width	mm			69.85±0.25		
Length	mm			100.20±0.25		
Thickness	mm			15.00 + 0.00/-0.50		
Weight	g			Up to 190g		

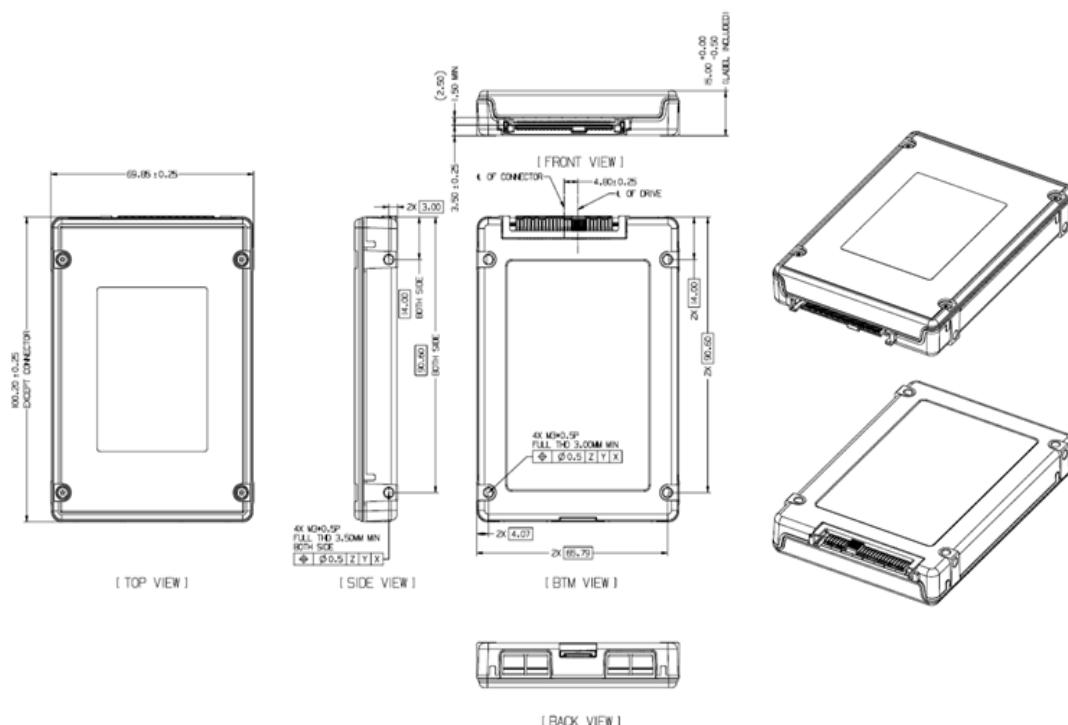


Figure 3. Mechanical Outline

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## 4.0 INTERFACE SPECIFICATION

The PCIe connector of PM1733a is compliant with SFF-8639 standard specification.

### 4.1 Connector Dimensions

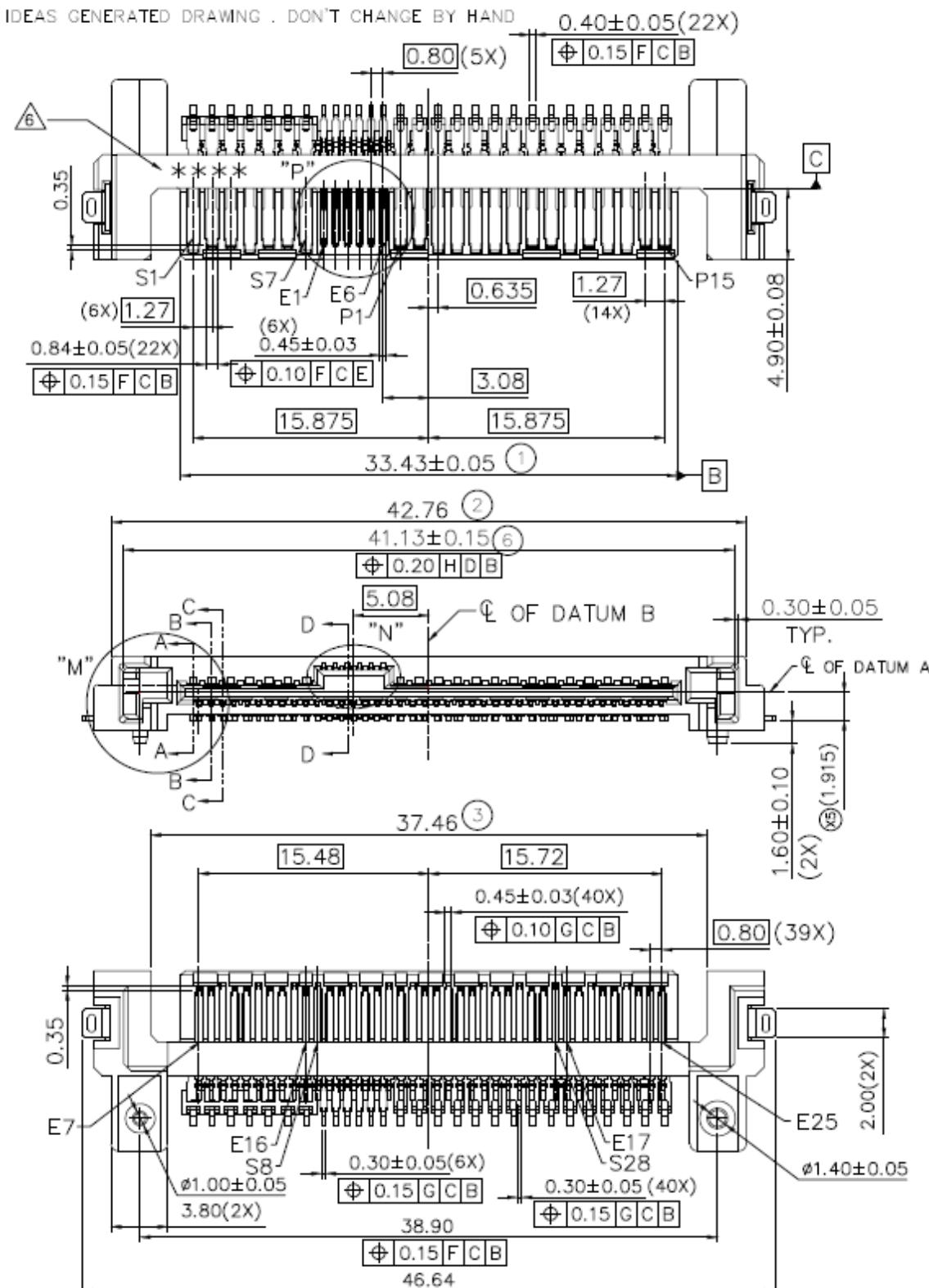


Figure 4. Layout of 2.5-inch Form Factor Connector Pins

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## 4.2 Connector Pin Assignments

[Table 21] U.2 interface pin-out

Pin #	Assignment	Description	Pin #	Assignment	Description
S1	GND	GND	E7	RefClk0+	PCIe Reference Clock + (primary port A)
S2	Not Used	Reserved <sup>1)</sup>	E8	RefClk0-	PCIe Reference Clock - (primary port A)
S3	Not Used	Reserved <sup>1)</sup>	E9	GND	GND
S4	GND	GND	E10	PETp0	PCIe Transmit+ (lane 0)
S5	Not Used	Reserved <sup>1)</sup>	E11	PETn0	PCIe Transmit- (lane 0)
S6	Not Used	Reserved <sup>1)</sup>	E12	GND	GND
S7	GND	GND	E13	PERn0	PCIe Receive- (lane 0)
E1	REFCLK1+	PCIe Reference Clock + (dual port, port B)	E14	PERp0	PCIe Receive+ (lane 0)
E2	REFCLK1-	PCIe Reference Clock - (dual port, port B)	E15	GND	GND
E3	3.3V AUX	Auxiliary Power (for SMBus access)	E16	HPT1	N/C
E4	ePERST1#	PCIe Reset (dual port, port B)	S8	Not Used	GND
E5	ePERST0#	PCIe Reset (primary port A)	S9	Not Used	Reserved <sup>1)</sup>
E6	Not Used	Interface Detect2(GND) <sup>1)</sup>	S10	Not Used	Reserved <sup>1)</sup>
P1	Not Used	N/C	S11	Not Used	GND
P2	Not Used	N/C	S12	Not Used	Reserved <sup>1)</sup>
P3	PWRDIS	Power Disable	S13	Not Used	Reserved <sup>1)</sup>
P4	IfDet #	Interface Detect (GND)	S14	Not Used	GND
P5	GND	GND	S15	HPT0	Host Port Type <sup>2)</sup>
P6	GND	GND	S16	GND	GND
P7	Not Used	N/C	S17	PETp1	PCIe Transmit+ (lane 1)
P8	Not Used	N/C	S18	PETn1	PCIe Transmit- (lane 1)
P9	Not Used	N/C	S19	GND	GND
P10	PRSNT #	Presence (N/C)	S20	PERn1	PCIe Receive- (lane 1)
P11	Activity	Drive Active	S21	PERp1	PCIe Receive+ (lane 1)
P12	GND	GND	S22	GND	GND
P13	12 V	Primary Power	S23	PETp2	PCIe Transmit+ (lane 2)
P14	12 V	Primary Power	S24	PETn2	PCIe Transmit- (lane 2)
P15	12 V	Primary Power	S25	GND	GND
			S26	PERn2	PCIe Receive- (lane 2)
			S27	PERp2	PCIe Receive+ (lane 2)
			S28	GND	GND
			E17	PETp3	PCIe Transmit+ (lane 3)
			E18	PETn3	PCIe Transmit- (lane 3)
			E19	GND	GND
			E20	PERn3	PCIe Receive- (lane 3)
			E21	PERp3	PCIe Receive+ (lane 3)
			E22	GND	GND
			E23	SMClk	SMBus Clock
			E24	SMDat	SMBus Data
			E25	DualPortEn#	Dual Port PCIe enable

**NOTE:**

1) Assigned for PCIe transmit/receive and auxiliary signals of U.3 interface support.

2) Determine which type of slot the device mated to. If S15 pin connected to GND through host, the device will operate as U.3 interface.

If slot has no connection(floated) to this pin, the device will operates as U.2 interface.

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[Table 22] U.3 interface pin-out

Pin #	Assignment	Description	Pin #	Assignment	Description
S1	GND	GND	E7	RefClk0+	PCIe Reference Clock + (primary port A)
S2	TX p0	PCIe Transmit+ (lane 0)	E8	RefClk0-	PCIe Reference Clock - (primary port A)
S3	TX n0	PCIe Transmit- (lane 0)	E9	GND	GND
S4	GND	GND	E10	Not Used	Reserved <sup>1)</sup>
S5	RX n0	PCIe Receive- (lane 0)	E11	Not Used	Reserved <sup>1)</sup>
S6	RX p0	PCIe Receive+ (lane 0)	E12	GND	GND
S7	GND	GND	E13	Not Used	Reserved <sup>1)</sup>
E1	REFCLK1+	PCIe Reference Clock + (dual port, port B)	E14	Not Used	Reserved <sup>1)</sup>
E2	REFCLK1-	PCIe Reference Clock - (dual port, port B)	E15	GND	GND
E3	3.3V AUX	Auxiliary Power (for SMBus access)	E16	HPT1	N/C
E4	ePERST1#	PCIe Reset (dual port, port B)	S8	Not Used	GND
E5	ePERST0#	PCIe Reset (primary port A)	S9	TX p1	PCIe Transmit+ (lane 1)
E6	IFDET2#	Interface Detect2	S10	TX n1	PCIe Transmit- (lane 1)
P1	Not Used	N/C	S11	Not Used	GND
P2	Not Used	N/C	S12	Not Used	PCIe Receive- (lane 1)
P3	PWRDIS	Power Disable	S13	Not Used	PCIe Receive+ (lane 1)
P4	IfDet #	Interface Detect (GND)	S14	Not Used	GND
P5	GND	GND	S15	HPT0	Host Port Type <sup>2)</sup>
P6	GND	GND	S16	GND	GND
P7	Not Used	N/C	S17	PETp1	PCIe Transmit+ (lane 1)
P8	Not Used	N/C	S18	PETn1	PCIe Transmit- (lane 1)
P9	Not Used	N/C	S19	GND	GND
P10	PRSNT #	Presence (N/C)	S20	PERn1	PCIe Receive- (lane 1)
P11	Activity	Drive Active	S21	PERp1	PCIe Receive+ (lane 1)
P12	GND	GND	S22	GND	GND
P13	12 V	Primary Power	S23	PETp2	PCIe Transmit+ (lane 2)
P14	12 V	Primary Power	S24	PETn2	PCIe Transmit- (lane 2)
P15	12 V	Primary Power	S25	GND	GND
			S26	PERn2	PCIe Receive- (lane 2)
			S27	PERp2	PCIe Receive+ (lane 2)
			S28	GND	GND
			E17	Not Used	Reserved <sup>1)</sup>
			E18	Not Used	Reserved <sup>1)</sup>
			E19	GND	GND
			E20	Not Used	Reserved <sup>1)</sup>
			E21	Not Used	Reserved <sup>1)</sup>
			E22	GND	GND
			E23	SMClk	SMBus Clock
			E24	SMDat	SMBus Data
			E25	DualPortEn#	Dual Port PCIe enable

**NOTE:**

1) Assigned for PCIe transmit/receive and auxiliary signals of U.2 interface support.

2) Determine which type of slot the device mated to. If S15 pin connected to GND through host, the device will operate as U.3 interface.

If slot has no connection(floated) to this pin, the device will operates as U.2 interface.

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## 5.0 PCI AND NVM EXPRESS REGISTERS

### 5.1 PCI Express Configuration Registers

#### 5.1.1 PCI Register Summary

[Table 23] PCI Register Summary

Start Address	Tag	Name	Type
00h	TYPE0_HDR	PCI Header	PCI Configuration Header Space
40h	PM_CAP	PCI Power Management Capability	PCI Capability
70h	PCIE_CAP	PCI Express Capability	PCI Capability
B0h	MSIX_CAP	MSI-X Capability	PCI Capability
100h	AER_CAP	Advanced Error Reporting (AER) Capability	PCIe Extended Capability
148h	DEV_CAP	Device Serial Number Capability	PCIe Extended Capability
168h	ARI_CAP	Alternative Routing-ID (ARI) Capability	PCIe Extended Capability
178h	SPCIE_CAP	Secondary PCI Express Capability (Gen.3) Capability	PCIe Extended Capability
198h	PL16G_CAP	Physical Layer 16.0 GT/s Capability	PCIe Extended Capability
1C0h	MARGIN_CAP	Margining Extended Capability Header	PCIe Extended Capability
1E8h	SRIOV_CAP	Single Root I/O Virtualization (SR-IOV) Capability	PCIe Extended Capability
3A4h	DLINK_CAP	Data Link Feature Extended Capability	PCIe Extended Capability

#### 5.1.2 PCI Configuration Header Space Registers Detail

##### 5.1.2.1 PCI Configuration Header Space Registers

[Table 24] PCI Header Space Summary

Start Address	End Address	Symbol	Description
00h	03h	ID	Identifiers
04h	05h	CMD	Command Register
06h	07h	STS	Status Register
08h	08h	REVID	Revision ID
09h	0Bh	CC	Class Codes
0Ch	0Ch	CLS	Cache Line Size
0Dh	0Dh	MLT	Master Latency Timer
0Eh	0Eh	HTYPE	Header Type
0Fh	0Fh	BIST	Built in Self Test
10h	13h	MLBAR (BAR0)	Memory Register Base Address (Lower 32-bit)
14h	17h	MUBAR (BAR1)	Memory Register Base Address (Upper 32-bit)
18h	1Bh	IDBAR (BAR2)	Reserved
1Ch	1Fh	BAR3	Reserved
20h	23h	BAR4	Reserved
24h	27h	BAR5	Reserved
28h	2Bh	CCPTR	CardBus CIS Pointer
2Ch	2Fh	SS	Subsystem Identifiers
30h	33h	EXPROM	Expansion ROM Base Address
34h	34h	CAP	Capabilities Pointer
35h	3Bh	R	Reserved
3Ch	3Dh	INTR	Interrupt Information
3Eh	3Eh	MGNT	Minimum Grant
3Fh	3Fh	MLAT	Maximum Latency

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[Table 25] Identifier Register

Bits	Type	Default Value	Description
31:16	RO	A825h	Device ID
0:15	RO	144Dh	Vendor ID

[Table 26] Command Register

Bits	Type	Default Value	Description
15:11	RO	0	Reserved
10	RW	0	Interrupt Disable
9	RO	0	Fast Back-to-Back Enable (N/A)
8	RW	0	SERR# Enable
7	RO	0	IDSEL Stepping / Wait Cycle Control (N/A)
6	RW	0	Parity Error Response Enable
5	RO	0	VGA Palette Snooping Enable (N/A)
4	RO	0	Memory Write and Invalidate Enable (N/A)
3	RO	0	Special Cycle Enable (N/A)
2	RW	0	Bus Master Enable
1	RW	0	Memory Space Enable
0	RW	0	I/O Space Enable

[Table 27] Status Register

Bits	Type	Default Value	Description
15	RW1C	0	Detected Parity Error
14	RW1C	0	Signaled System Error
13	RW1C	0	Received Master Abort
12	RW1C	0	Received Target Abort
11	RW1C	0	Signaled Target Abort (N/A)
10:9	RO	0	DEVSEL Timing (N/A)
8	RW1C	0	Master Data Parity Error Detected (N/A)
7	RO	0	Fast Back-to-Back Transaction Capable (N/A)
6	RO	0	Reserved
5	RO	0	66MHz Capable (N/A)
4	RO	1h	Capabilities List
3	RO	0	Interrupt Status
2:1	RO	0	Reserved
0	RO	0	Reserved

[Table 28] Revision ID Register

Bits	Type	Default Value	Description
7:0	RO	00h	Controller Hardware Revision ID

[Table 29] Class Code Register

Bits	Type	Default Value	Description
23:16	RO	01h	Base Class Code
15:8	RO	08h	Sub Class Code
7:0	RO	02h	Programming Interface

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[Table 30] Cache Line Size Register

Bits	Type	Default Value	Description
7:0	RW	0	Cache Line Size (N/A)

[Table 31] Master Latency Timer Register

Bits	Type	Default Value	Description
7:0	RO	0	Master Latency Timer (N/A)

[Table 32] Header Type Register

Bits	Type	Default Value	Description
7	RO	0	Multi-function Device (N/A)
6:0	RO	0	Reserved

[Table 33] Built In Self Test Register

Bits	Type	Default Value	Description
7	RO	0	Built In Self Test (N/A)
6	RO	0	Built In Self Test (N/A)
5:4	RO	0	Built In Self Test (N/A)
3:0	RO	0	Built In Self Test (N/A)

[Table 34] Memory Register Base Address Lower 32-bits (BAR0) Register

Bits	Type	Default Value	Description
31:15	RW	0	Base Address
14:4	RO	0	Reserved
3	RO	0	Pre-Fetchable
2:1	RO	2h	Address Type (64-bit)
0	RO	0	Memory Space Indicator (MEMSI)

[Table 35] Memory Register Base Address Upper 32-bits (BAR1)

Bits	Type	Default Value	Description
31:0	RW	0	Base Address

[Table 36] Index/Data Pair Register Base Address (BAR2) Register

Bits	Type	Default Value	Description
31:0	RO	0	N/A

[Table 37] BAR3 Register

Bits	Type	Default Value	Description
31:0	RO	0	N/A

[Table 38] Vendor Specific BAR4 Register

Bits	Type	Default Value	Description
31:0	RO	0	N/A

[Table 39] Vendor Specific BAR5 Register

Bits	Type	Default Value	Description
31:0	RO	0	N/A

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[Table 40] Cardbus CIS Pointer Register

Bits	Type	Default Value	Description
31:0	RO	0	N/A

[Table 41] Subsystem Identifier Register

Bits	Type	Default Value	Description
31:16	RO	1TB: A807h 2TB: A808h 4TB: A809h 8TB: A80Ah 16TB: A80Bh 32TB: A80Ch	Subsystem ID
15:0	RO	144Dh	Subsystem Vendor ID

[Table 42] Expansion ROM Register

Bits	Type	Default Value	Description
31:17	RW	0	Expansion ROM Base Address
16:1	RO	0	Reserved
0	RW	0	Expansion ROM Enable/Disable

[Table 43] Capabilities Pointer Register

Bits	Type	Default Value	Description
7:0	RO	40h	Capability Pointer

[Table 44] Interrupt Information Register

Bits	Type	Default Value	Description
15:8	RO	01h	Interrupt Pin
7:0	RW	0	Interrupt Line

[Table 45] Minimum Grant Register

Bits	Type	Default Value	Description
7:0	RO	0	Minimum Grant (N/A)

[Table 46] Maximum Latency Register

Bits	Type	Default Value	Description
7:0	RO	0	Maximum Latency (N/A)

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## 5.1.3 PCI Capability Registers

### 5.1.3.1 PCI Power Management Capability

[Table 47] PCI Power Management Capability Register Summary

Start Address	End Address	Symbol	Description
40h	40h	PCIPM_ID	PCI Power Management Capability ID
41h	41h	NEXTCAP	Next Capability Pointer
42h	43h	PCIPM_CAP	PC Power Management Capabilities
44h	45h	PCIPM_CS	PCI Power Management Control and Status
46h	46h	PCIPM_CSR_BSE	PMCSR_BSE Bridge Extensions
47h	47h	PCIPM_DATA	Data

[Table 48] PCI Power Management Capability ID Register

Bits	Type	Default Value	Description
15:8	RO	70h	Next Capability Pointer
7:0	RO	1h	Capability ID

[Table 49] PCI Power Management Capability Register

Bits	Type	Default Value	Description
15:11	RO	0	PME Support (N/A)
10	RO	0	D2 Support (N/A)
9	RO	0	D1 Support (N/A)
8:6	RO	0	AUX current (N/A)
5	RO	0	Device Specific Initialization (N/A)
4	RsvdP	0	Reserved
3	RO	0	PME Clock (N/A)
2:0	RO	3h	Version (Support for PCIe Power Management Interface Spec revision 1.2)

[Table 50] PCI Power Management Control and Status Register

Bits	Type	Default Value	Description
31:24	RsvdP	0	Data register (N/A)
23	RO	0	Bus Power/Clock Enable (N/A)
22	RO	0	B2, B3 support (N/A)
21:16	RsvdP	0	Reserved
15	RO	0	PME Status (N/A)
14:13	RO	0	Data scale (N/A)
12:9	RO	0	Data scale (N/A)
8	RWS	0	PME Enable (N/A)
7:4	RsvdP	0	Reserved
3	RO	1h	No Soft Reset
2	RsvdP	0	Reserved
1:0	RW	0	Power State

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### 5.1.3.2 PCI Express Capability

[Table 51] PCI Capability Register Summary

Start Address	End Address	Symbol	Description
70h	71h	PCIE_ID	PCI Express Capability ID
72h	73h	PCIE_CAP	PCI Express Capabilities
74h	77h	PCIE_DCAP	PCI Express Device Capabilities
78h	79h	PCIE_DC	PCI Express Device Control
7Ah	7Bh	PCIE_DS	PCI Express Device Status
7Ch	7Fh	PCIE_LCAP	PCI Express Link Capabilities
80h	81h	PCIE_LC	PCI Express Link Control
82h	83h	PCIE_LS	PCI Express Link Status
94h	97h	PCIE_DCAP2	PCI Express Device Capabilities 2
98h	99h	PCIE_DC2	PCI Express Device Control 2
9Ah	9Bh	PCIE_DS2	PCI Express Device Status 2
9Ch	9Fh	PCIE_LCAP2	PCI Express Link Capabilities 2
A0h	A1h	PCIE_LC2	PCI Express Link Control 2
A2h	A3h	PCIE_LS2	PCI Express Link Status 2

[Table 52] PCI Express Capability ID Register

Bits	Type	Default Value	Description
15:8	RO	B0h	Next Capability Pointer
7:0	RO	10h	Capability ID

[Table 53] PCI Express Capabilities Register

Bits	Type	Default Value	Description
15:14	RsvdP	0	Reserved
13:9	RO	0	Interrupt Message Number
8	HWInit	0	Slot Implementation (N/A)
7:4	RO	0	Device/Port Type
3:0	RO	2h	Capability Version

[Table 54] PCI Express Device Capabilities Register

Bits	Type	Default Value	Description
31:29	RsvdP	0	Reserved
28	RO	1h	Function Level Reset Capability
27:26	RO	0	Captured Slot Power Limit Scale
25:18	RO	0	Captured Slot Power Limit Value
17:16	RsvdP	0	Reserved
15	RO	1h	Role-based Error Reporting
14:12	RO	0	Reserved
11:9	RO	7h	Endpoint L1 Acceptable Latency
8:6	RO	7h	Endpoint L0 Acceptable Latency
5	RO	1h	Extended Tag Field Supported
4:3	RO	0	Phantom Functions Supported
2:0	RO	2h	Max Payload Size Supported

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[Table 55] PCI Express Device Control Register

Bits	Type	Default Value	Description
15	RW	0	Initiate Function Level Reset
14:12	RW	2h	Max Read Request Size
11	RW	1h	Enable No Snoop
10	RWS	0	Aux Power PM Enable (N/A)
9	RW	0	Phantom Functions Enable (N/A)
8	RW	1h	Extended Tag Enable
7:5	RW	0	Max Payload Size
4	RW	1h	Enable Relaxed Ordering
3	RW	0	Unsupported Request Reporting Enable
2	RW	0	Fatal Error Reporting Enable
1	RW	0	Non-Fatal Error Reporting Enable
0	RW	0	Correctable Error Reporting Enable

[Table 56] PCI Express Device Status Register

Bits	Type	Default Value	Description
15:6	RsvdZ	0	Reserved
5	RO	0	Transactions Pending
4	RO	0	Aux Power Detected
3	RW1C	0	Unsupported Request Detected
2	RW1C	0	Fatal Error Detected
1	RW1C	0	Non-Fatal Error Detected
0	RW1C	0	Correctable Error Detected

[Table 57] PCI Express Link Capabilities Register

Bits	Type	Default Value	Description
31:24	HWInit	0 (Port 0)	Port Number
23	RsvdP	0	Reserved
22	HWInit	1h	ASPM Optionality Compliance
21	RO	0	Link Bandwidth Notification Capability (N/A)
20	RO	0	Data Link Layer Link Active Reporting Capable (N/A)
19	RO	0	Surprise Down Error Reporting Capable (N/A)
18	RO	0	Clock Power Management
17:15	RO	6h	L1 Exit Latency
14:12	RO	7h	L0s Exit Latency
11:10	RO	0	Active State Power Management Support
9:4	RO	Single Port: 4h (x4 link) Dual Port: 2h (x2 link)	Maximum Link Width
3:0	RO	4h	Max Link Speeds

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[Table 58] PCI Express Link Control Register

Bits	Type	Default Value	Description
15:14	RW/RsvdP	0	Reserved
13:12	RsvdP	0	Rsvd
11	RsvdP	0	Link Autonomous Bandwidth interrupt enable (N/A)
10	RsvdP	0	Link Bandwidth management interrupt enable (N/A)
9	RW	0	Hardware Autonomous Width Disable
8	RW	0	Enable Clock Power Management
7	RW	0	Extended Sync
6	RW	0	Common Clock Configuration
5	RsvdP	0	Retrain Link (N/A)
4	RsvdP	0	Link Disable (N/A)
3	RW	0	Read Completion Boundary (N/A)
2	RsvdP	0	Reserved
1:0	RW	0	Active State Power Management Control

[Table 59] PCI Express Link Status Register

Bits	Type	Default Value	Description
15	RsvdP	0	Link Autonomous Bandwidth Status (N/A)
14	RsvdP	0	Link Bandwidth Management Status (N/A)
13	RO	0	Data Link Layer Link Active
12	HwInit	1h	Slot Clock Configuration
11	RO	0	Link Training (N/A)
10	RO	0	Reserved
9:4	RO	1h	Negotiated Link Width
3:0	RO	1h	Current Link Speed

[Table 60] PCI Express Device Capabilities 2 Register

Bits	Type	Default Value	Description
31	HwInit	0	Reserved
30:24	RsvdP	0	Reserved
23:22	HwInit	0	Max End-End TLP Prefixes (N/A)
21	HwInit	0	End-End TLP Prefix Supported (N/A)
20	RO	0	Extended Format Field Supported (N/A)
19:18	HwInit	0	OBFF Supported (N/A)
17	HwInit	0	10-Bit Tag Requester Supported
16	HwInit	1h	10-Bit Tag Completer Supported
15:14	HwInit	0	LN System CLS (N/A)
13:12	RO	0	TPH Completer Supported (N/A)
11	RO	0	Latency Tolerance Reporting Supported
10	HwInit	0	No RO-enabled PR-PR Passing (N/A)
9	RO	0	128-bit CAS Completer Supported (N/A)
8	RO	0	64-bit Atomic Op Completer Supported (N/A)
7	RO	0	32-bit Atomic Op Completer Supported (N/A)
6	RO	0	Atomic Op Routing Supported (N/A)
5	RO	0	ARI Forwarding Supported (N/A)
4	RO	1h	Completion Timeout Disable Supported
3:0	HwInit	Fh	Completion Timeout Ranges Supported

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[Table 61] PCI Express Device Control 2 Register

Bits	Type	Default Value	Description
15	RsvdP	0	End-to-end TLP Prefix Blocking (N/A)
14:13	RW/RsvdP	0	OBFF Enable (N/A)
12:11	RsvdP	0	Reserved
10	RW/RsvdP	0	Latency Tolerance Reporting Mechanism Enable
9	RW	0	IDO Completion enable (N/A)
8	RW	0	IDO Request Enable (N/A)
7	RW	0	AtomicOp Egress Blocking (N/A)
6	RW	0	AtomicOp Requester Enable (N/A)
5	RW	0	ARI forwarding supported (N/A)
4	RW	0	Completion Timeout Disable
3:0	RW	0	Completion Timeout Value

[Table 62] PCI Express Device Status 2 Register

Bits	Type	Default Value	Description
15:0	RsvdZ	0	Reserved

[Table 63] PCI Express Link Capabilities 2 Register

Bits	Type	Default Value	Description
31	RO	0	Reserved
30:25	RsvdP	0	Reserved
24	RsvdP	1h	Two Retimers Presence Detect Supported
23	HWInit	1h	Retimer Presence Detect Supported
22:16	HWInit	0	Lower SKP OS Reception Supported Speed Vector (N/A)
15:9	HWInit	0	Lower SKP OS Generation Supported Speed Vector (N/A)
8	RO	0	Cross-Link Supported (N/A)
7:1	RO	Fh	Supported Link Speeds
0	RsvdP	0	Reserved

[Table 64] PCI Express Link Control 2 Register

Bits	Type	Default Value	Description
15:12	RWS/RsvdP	0	Compliance De-emphasis
11	RWS/RsvdP	0	Compliance SOS
10	RWS/RsvdP	0	Enter Modified Compliance
9:7	RWS/RsvdP	0	Transmit Margin
6	HWInit	0	Select De-Emphasis (N/A)
5	RWS/RsvdP	0	Hardware Autonomous Speed Disable
4	RWS/RsvdP	0	Enter Compliance
3:0	RWS/RsvdP	4h	Target Link Speed

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[Table 65] PCI Express Link Status 2 Register

Bits	Type	Default Value	Description
15:10	RsvdP	0	Reserved
9:8	RO	1h	Crosslink Resolution
7:6	RsvdP	0	Reserved
5	RW1CS	0	Link Equalization Request 8.0GT/s
4	ROS	0	Equalization 8.0GT/s Phase 3 Successful
3	ROS	0	Equalization 8.0GT/s Phase 2 Successful
2	ROS	0	Equalization 8.0GT/s Phase 1 Successful
1	ROS	0	Equalization 8.0GT/s Complete
0	RO	1h	Current De-Emphasis

### 5.1.3.3 MSI-X Capability

[Table 66] MSI-X Capability Summary

Start Address	End Address	Symbol	Description
B0h	B1h	MSIX_ID	MSI-X Capability ID
B2h	B3h	MSIX_CAP	MSI-X Message Control
B4h	B7h	MSIX_TBL	MSI-X Table Offset and Table BIR
B8h	BBh	MSIX_PBA	MSI-X PBA Offset and PBA BIR

[Table 67] MSI-X Identifier Register

Bits	Type	Default Value	Description
15:8	RO	0h	Next Capability Pointer
7:0	RO	11h	Capability ID

[Table 68] MSI-X Control Register

Bits	Type	Default Value	Description
15	RW	0	MSI-X Enable
14	RW	0	Function Mask
13:11	RsvdP	0	Reserved
10:0	RO	3Fh	Table Size

[Table 69] MSI-X Table Offset Register

Bits	Type	Default Value	Description
31:3	RO	800h	Table Offset
2:0	RO	0	Table BIR

[Table 70] MSI-X Pending Bit Array Offset Register

Bits	Type	Default Value	Description
31:3	RO	600h	Pending Bit Array Offset
2:0	RO	0	Pending Bit Array BIR

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## 5.1.4 PCI Extended Capability Details

### 5.1.4.1 Advanced Error Reporting Registers

[Table 71] Advanced Error Reporting Capability Summary

Start Address	End Address	Symbol	Description
100h	103h	AER_ID	AER Capability ID
104h	107h	AER_UCES	AER Uncorrectable Error Status
108h	10Bh	AER_UCEM	AER Uncorrectable Error Mask
10Ch	10Fh	AER_UCESEV	AER Uncorrectable Error Severity
110h	113h	AER_CES	AER Correctable Error Status
114h	117h	AER_CEM	AER Correctable Error Mask
118h	11Bh	AER_CC	AER Advanced Error Capabilities and Control
11Ch	12Bh	AER_HL	AER Header Log

[Table 72] AER Capability ID Register

Bits	Type	Default Value	Description
31:20	RO	148h	Next Capability Pointer
19:16	RO	2h	Capability Version
15:0	RO	1h	Capability ID

[Table 73] AER Uncorrectable Error Status Register

Bits	Type	Default Value	Description
31:27	RsvdZ	0	Reserved
26	RW1CS	0	Poisoned TLP Egress Blocked Status (N/A)
25	RW1CS	0	TLP Prefix Blocked Error Status (N/A)
24	RW1CS	0	Atomic Op Egress Blocked Status (N/A)
23	RW1CS	0	MC Blocked TLP Status (N/A)
22	RW1CS	0	Uncorrectable Internal Error Status
21	RW1CS	0	ACS Violation Status (N/A)
20	RW1CS	0	Unsupported Request Error Status
19	RW1CS	0	ECRC Error Status
18	RW1CS	0	Malformed TLP Status
17	RW1CS	0	Receiver Overflow Status
16	RW1CS	0	Unexpected Completion Status
15	RW1CS	0	Completer Abort Status
14	RW1CS	0	Completion Timeout Status
13	RW1CS	0	Flow Control Protocol Error Status
12	RW1CS	0	Poisoned TLP Status
11:6	RsvdZ	0	Reserved
5	RW1CS	0	Surprise Down Error Status (N/A)
4	RW1CS	0	Data Link Protocol Error Status
3:1	RsvdZ	0	Reserved
0	Undefined	0	Undefined

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[Table 74] AER Uncorrectable Error Mask Register

Bits	Type	Default Value	Description
31:27	RsvdP	0	Reserved
26	RWS	0	Poisoned TLP Egress Blocked Mask (N/A)
25	RWS	0	TLP Prefix Blocked Error Mask (N/A)
24	RWS	0	Atomic Op Egress Blocked Mask (N/A)
23	RWS	0	MC Blocked TLP Mask (N/A)
22	RWS	1h	Uncorrectable Internal Error Mask
21	RWS	0	ACS Violation Mask (N/A)
20	RWS	0	Unsupported Request Error Mask
19	RWS	0	ECRC Error Mask
18	RWS	0	Malformed TLP Mask
17	RWS	0	Receiver Overflow Mask
16	RWS	0	Unexpected Completion Mask
15	RWS	0	Completer Abort Mask
14	RWS	0	Completion Timeout Mask
13	RWS	0	Flow Control Protocol Error Mask
12	RWS	0	Poisoned TLP Mask
11:6	RsvdP	0	Reserved
5	RWS	0	Surprise Down Error Mask (N/A)
4	RWS	0	Data Link Protocol Error Mask
3:1	RsvdP	0	Reserved
0	Undefined	0	Undefined

[Table 75] AER Uncorrectable Error Severity Register

Bits	Type	Default Value	Description
31:27	RsvdP	0	Reserved
26	RWS	0	Poisoned TLP Egress Blocked Severity (N/A)
25	RWS	0	TLP Prefix Blocked Error Severity (N/A)
24	RWS	0	Atomic Op Egress Blocked Severity (N/A)
23	RWS	0	MC Blocked TLP Severity (N/A)
22	RWS	1h	Uncorrectable Internal Error Severity
21	RWS	0	ACS Violation Severity (N/A)
20	RWS	0	Unsupported Request Error Severity
19	RWS	0	ECRC Error Severity
18	RWS	1h	Malformed TLP Severity
17	RWS	1h	Receiver Overflow Severity
16	RWS	0	Unexpected Completion Severity
15	RWS	0	Completer Abort Severity
14	RWS	0	Completion Timeout Severity
13	RWS	1h	Flow Control Protocol Error Severity
12	RWS	0	Poisoned TLP Severity
11:6	RsvdP	0	Reserved
5	RWS	1h	Surprise Down Error Severity (N/A)
4	RWS	1h	Data Link Protocol Error Severity
3:1	RsvdP	0	Reserved
0	Undefined	0	Undefined

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[Table 76] AER Correctable Error Status Register

Bits	Type	Default Value	Description
31:16	RsvdZ	0	Reserved
15	RW1CS	0	Header Log Overflow Status
14	RW1CS	0	Corrected Internal Error Status
13	RW1CS	0	Advisory Non-Fatal Error Status
12	RW1CS	0	Replay Timer Timeout Status
11:9	RsvdZ	0	Reserved
8	RW1CS	0	Replay Number Rollover Status
7	RW1CS	0	Bad DLLP Status
6	RW1CS	0	Bad TLP Status
5:1	RsvdZ	0	Reserved
0	RW1CS	0	Received Error Status

[Table 77] AER Correctable Error Mask Register

Bits	Type	Default Value	Description
31:16	RsvdP	0	Reserved
15	RWS	1h	Header Log Overflow Mask
14	RWS	1h	Corrected Internal Error Mask
13	RWS	1h	Advisory Non-Fatal Error Mask
12	RWS	0	Replay Timer Timeout Mask
11:9	RsvdP	0	Reserved
8	RWS	0	Replay Number Rollover Mask
7	RWS	0	Bad DLLP Mask
6	RWS	0	Bad TLP Mask
5:1	RsvdP	0	Reserved
0	RWS	0	Received Error Mask

[Table 78] AER Capabilities and Control Register

Bits	Type	Default Value	Description
31:13	RsvdP	0	Reserved
12	RO	0	Completion Timeout Prefix/Header Log Capable (N/A)
11	ROS	0	TLP Prefix Log Present (N/A)
10	RWS	0	Multiple Header Recording Enable
9	RO	1h	Multiple Header Recording Capable
8	RWS	0	ECRC Check Enable
7	RO	1h	ECRC Check Capable
6	RWS	0	ECRC Generation Enable
5	RO	1h	ECRC Generation Capable
4:0	ROS	0	First Error Pointer

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[Table 79] AER Header Log Register

Bits	Type	Default Value	Description
127:120	ROS	0	Header Byte 0
119:112	ROS	0	Header Byte 1
111:104	ROS	0	Header Byte 2
103:96	ROS	0	Header Byte 3
95:88	ROS	0	Header Byte 4
87:80	ROS	0	Header Byte 5
79:72	ROS	0	Header Byte 6
71:64	ROS	0	Header Byte 7
63:56	ROS	0	Header Byte 8
55:48	ROS	0	Header Byte 9
47:40	ROS	0	Header Byte 10
39:32	ROS	0	Header Byte 11
31:24	ROS	0	Header Byte 12
23:16	ROS	0	Header Byte 13
15:8	ROS	0	Header Byte 14
7:0	ROS	0	Header Byte 15

### 5.1.4.2 Device serial number capability registers

[Table 80] Device serial number capability Summary

Start Address	End Address	Symbol	Description
148h	14Bh		Device Serial Number Extended Capability Header
14Ch	14Fh		Serial Number Register (Lower DW)
150h	153h		Serial Number Register (Upper DW)

[Table 81] Device Serial Number Extended Capability Header

Bits	Type	Default Value	Description
31:20	RO	168h	Next Capability Pointer
19:16	HwInit	1h	Capability Version
15:0	HwInit	3h	Serial number capability ID (Secondary PCI Express Extended capability)

[Table 82] Device Serial Number Register (Upper and Lower DW)

Bits	Type	Default Value	Description
63:0	RO	0	Device serial number register

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### 5.1.4.3 Alternative Routing-ID(ARI) Capability

[Table 83] Alternative Routing-ID(ARI) Capability Summary

Start Address	End Address	Symbol	Description
168h	16Bh		Alternative Routing-ID(ARI) Capability Header
16Ch	16Dh		ARI Capability Register
16Eh	16Fh		ARI Control Register

[Table 84] Alternative Routing-ID(ARI) Capability Header

Bits	Type	Default Value	Description
31:20	RO	178h	Next Capability Pointer
19:16	RO	1h	Capability Version
15:0	RO	Eh	PCI Express Extended Capability ID

[Table 85] ARI Capability Register

Bits	Type	Default Value	Description
15:8	RO	0	Next Function Number
7:2	RO	0	RsvdP
1	RO	0	ACS Function Groups Capability
0	RO	0	MFVC Function Groups Capability

[Table 86] ARI Control Register

Bits	Type	Default Value	Description
15:7	RsvdP	0	RsvdP
6:4	RW	0	Function Group
3:2	RsvdP	0	RsvdP
1	RW	0	ACS Function Groups Enable
0	RW	0	MFVC Function Groups Enable

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### 5.1.4.4 Secondary PCI Express Capability

[Table 87] Secondary PCI Express Capability Summary

Start Address	End Address	Symbol	Description
178h	17Bh	SPE_ID	Secondary PCI Express Capability
17Ch	17Fh	SPE_LC3	PCI Express Link Control 3
180h	183h	SPE_LE	PCI Express Lane Error Status
184h	185h	SPE_L0EC	PCI Express Lane 0 Equalization Control
186h	187h	SPE_L1EC	PCI Express Lane 1 Equalization Control
188h	189h	SPE_L2EC	PCI Express Lane 2 Equalization Control
18Ah	18Bh	SPE_L3EC	PCI Express Lane 3 Equalization Control

[Table 88] Secondary PCI Express Capability ID Register

Bits	Type	Default Value	Description
31:20	RO	198h	Next Capability offset
19:16	RO	1h	Capability Version
15:0	RO	19h	Capability ID (Secondary PCI Express Extended capability)

[Table 89] PCI Express Link Control 3 Register

Bits	Type	Default Value	Description
31:16	RsvdP	0	Reserved
15:9	RW	0	Enable Lower SKP OS Generation Vector (N/A)
8:2	RsvdP	0	Reserved
1	RW	0	Link Equalization Request Interrupt Enable (N/A)
0	RW	0	Perform Equalization (N/A)

[Table 90] PCI Express Lane Error Status Register

Bits	Type	Default Value	Description
31:4	RsvdP	0	Reserved
3:0	RW1CS	0	Lane Error Status Bits

[Table 91] Lane 0 Equalization Control Register

Bits	Type	Default Value	Description
15	RsvdP	0	Reserved
14:12	HWInit/RO	7h	Upstream Port 8.0T/s Receiver Preset Hint
11:8	HWInit/RO	Fh	Upstream Port 8.0T/s Transmitter Preset
7	RsvdZ	0	Reserved
6:4	HWInit/RsvdP	0	Downstream Port 8.0T/s Receiver Preset Hint (N/A)
3:0	HWInit/RsvdP	0	Downstream Port 8.0T/s Transmitter Preset (N/A)

[Table 92] Lane 1 Equalization Control Register

Bits	Type	Default Value	Description
15	RsvdP	0	Reserved
14:12	HWInit/RO	7h	Upstream Port 8.0T/s Receiver Preset Hint
11:8	HWInit/RO	Fh	Upstream Port 8.0T/s Transmitter Preset
7	RsvdZ	0	Reserved
6:4	HWInit/RsvdP	0	Downstream Port 8.0T/s Receiver Preset Hint (N/A)
3:0	HWInit/RsvdP	0	Downstream Port 8.0T/s Transmitter Preset (N/A)

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[Table 93] Lane 2 Equalization Control Register

Bits	Type	Default Value	Description
15	RsvdP	0	Reserved
14:12	HWInit/RO	7h	Upstream Port 8.0T/s Receiver Preset Hint
11:8	HWInit/RO	Fh	Upstream Port 8.0T/s Transmitter Preset
7	RsvdZ	0	Reserved
6:4	HWInit/RsvdP	0	Downstream Port 8.0T/s Receiver Preset Hint (N/A)
3:0	HWInit/RsvdP	0	Downstream Port 8.0T/s Transmitter Preset (N/A)

[Table 94] Lane 3 Equalization Control Register

Bits	Type	Default Value	Description
15	RsvdP	0	Reserved
14:12	HWInit/RO	7h	Upstream Port 8.0T/s Receiver Preset Hint
11:8	HWInit/RO	Fh	Upstream Port 8.0T/s Transmitter Preset
7	RsvdZ	0	Reserved
6:4	HWInit/RsvdP	0	Downstream Port 8.0T/s Receiver Preset Hint (N/A)
3:0	HWInit/RsvdP	0	Downstream Port 8.0T/s Transmitter Preset (N/A)

### 5.1.4.5 Physical Layer 16.0 GT/s Capability

[Table 95] Physical Layer 16.0 GT/s Capability Summary

Start Address	End Address	Symbol	Description
198h	19Bh		Physical Layer 16.0 GT/s Extended Capability Header
19Ch	19Fh		16.0 GT/s Capabilities Register
1A0h	1A3h		16.0 GT/s Control Register
1A4h	1A7h		16.0 GT/s Status Register
1A8h	1ABh		16.0 GT/s Local Data Parity Mismatch Status Register
1ACh	1AFh		16.0 GT/s First Retimer Data Parity Mismatch Status Register
1B0h	1B3h		16.0 GT/s Second Retimer Data Parity Mismatch Status Register
1B4h	1B7h		Reserved
1B8h	1BBh		16.0 GT/s Control Register for Lane 0-3
1BCh	1BFh		16.0 GT/s Control Register for Lane 4-7

[Table 96] Physical Layer 16.0 GT/s Extended Capability Header

Bits	Type	Default Value	Description
31:20	RO	1C0h	Next Capability Pointer
19:16	RO	1h	Capability Version
15:0	RO	26h	Capability ID (Secondary PCI Express Extended capability)

[Table 97] 16.0 GT/s Capabilities Register

Bits	Type	Default Value	Description
31:0	RsvdP	0	Reserved

[Table 98] 16.0 GT/s Control Register

Bits	Type	Default Value	Description
31:0	RsvdP	0	Reserved

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[Table 99] 16.0 GT/s Status Register

Bits	Type	Default Value	Description
31:5	RsvdZ	0	Reserved
4	RW1CS/RsvdZ	0	Link Equalization Request 16.0 GT/s
3	ROS/RsvdZ	0	Equalization 16.0 GT/s Phase 3 Successful
2	ROS/RsvdZ	0	Equalization 16.0 GT/s Phase 2 Successful
1	ROS/RsvdZ	0	Equalization 16.0 GT/s Phase 1 Successful
0	ROS/RsvdZ	0	Equalization 16.0 GT/s Complete

[Table 100] 16.0 GT/s Local Data Parity Mismatch Status Register

Bits	Type	Default Value	Description
31:8	RsvdP	0	Reserved
7:0	RW1CS	0	Local Data Parity Mismatch Status

[Table 101] 16.0 GT/s First Retimer Data Parity Mismatch Status Register

Bits	Type	Default Value	Description
31:8	RsvdP	0	Reserved
7:0	RW1CS	0	First Retimer Data Parity Mismatch Status

[Table 102] 16.0 GT/s Second Retimer Data Parity Mismatch Status Register

Bits	Type	Default Value	Description
31:8	RsvdP	0	Reserved
7:0	RW1CS	0	Second Retimer Data Parity Mismatch Status

[Table 103] Reserved

Bits	Type	Default Value	Description
31:0	RsvdP	0	Reserved

[Table 104] 16.0 GT/s Control Register for Lane 0-3

Bits	Type	Default Value	Description
31:28	HwInit/RO	Fh	Upstream Port 16.0 GT/s Transmitter Preset (Lane 3)
27:24	HwInit/RsvdP	0h	Downstream Port 16.0 GT/s Transmitter Preset (Lane 3)
23:20	HwInit/RO	Fh	Upstream Port 16.0 GT/s Transmitter Preset (Lane 2)
19:16	HwInit/RsvdP	0h	Downstream Port 16.0 GT/s Transmitter Preset (Lane 2)
15:12	HwInit/RO	Fh	Upstream Port 16.0 GT/s Transmitter Preset (Lane 1)
11:8	HwInit/RsvdP	0h	Downstream Port 16.0 GT/s Transmitter Preset (Lane 1)
7:4	HwInit/RO	Fh	Upstream Port 16.0 GT/s Transmitter Preset (Lane 0)
3:0	HwInit/RsvdP	0h	Downstream Port 16.0 GT/s Transmitter Preset (Lane 0)

[Table 105] 16.0 GT/s Control Register for Lane 4-7

Bits	Type	Default Value	Description
31:28	HwInit/RO	Fh	Upstream Port 16.0 GT/s Transmitter Preset (Lane 7)
27:24	HwInit/RsvdP	0h	Downstream Port 16.0 GT/s Transmitter Preset (Lane 7)
23:20	HwInit/RO	Fh	Upstream Port 16.0 GT/s Transmitter Preset (Lane 6)
19:16	HwInit/RsvdP	0h	Downstream Port 16.0 GT/s Transmitter Preset (Lane 6)
15:12	HwInit/RO	Fh	Upstream Port 16.0 GT/s Transmitter Preset (Lane 5)
11:8	HwInit/RsvdP	0h	Downstream Port 16.0 GT/s Transmitter Preset (Lane 5)
7:4	HwInit/RO	Fh	Upstream Port 16.0 GT/s Transmitter Preset (Lane 4)
3:0	HwInit/RsvdP	0h	Downstream Port 16.0 GT/s Transmitter Preset (Lane 4)

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### 5.1.4.6 Margining Extended Capability Header

[Table 106] Margining Extended Capability Header Summary

Start Address	End Address	Symbol	Description
1C0h	1C3h		Margining Extended Capability Header
1C4h	1C5h		Margining Port Capabilities Register
1C6h	1C7h		Margining Port Status Register
1C8h	1C9h		Margining Lane Control Register (Lane 0)
1CAh	1CBh		Margining Lane Control Register (Lane 0)
1CCh	1CDh		Margining Lane Control Register (Lane 1)
1CEh	1CFh		Margining Lane Control Register (Lane 1)
1D0h	1D1h		Margining Lane Control Register (Lane 2)
1D2h	1D3h		Margining Lane Control Register (Lane 2)
1D4h	1D5h		Margining Lane Control Register (Lane 3)
1D6h	1D7h		Margining Lane Control Register (Lane 3)
1D8h	1D9h		Margining Lane Control Register (Lane 4)
1DAh	1DBh		Margining Lane Control Register (Lane 4)
1DCh	1DDh		Margining Lane Control Register (Lane 5)
1DEh	1DFh		Margining Lane Control Register (Lane 5)
1E0h	1E1h		Margining Lane Control Register (Lane 6)
1E2h	1E3h		Margining Lane Control Register (Lane 6)
1E4h	1E5h		Margining Lane Control Register (Lane 7)
1E6h	1E7h		Margining Lane Control Register (Lane 7)

[Table 107] Physical Layer 16.0 GT/s Margining Capability

Bits	Type	Default Value	Description
31:20	RO	1E8h	Next Capability Pointer
19:16	RO	1h	Capability Version
15:0	RO	27h	PCI Express Extended Capability ID

[Table 108] Margining Port Capabilities Register

Bits	Type	Default Value	Description
15:1	RsvdP	0	Reserved
0	HWInit	0	Margining uses Driver Software

[Table 109] Margining Port Status Register

Bits	Type	Default Value	Description
15:2	RsvdZ	0	Reserved
1	RO	1h	Margining Software Ready
0	RO	1h	Margining Ready

[Table 110] Margining Lane Control Register (Lane 0)

Bits	Type	Default Value	Description
15:8	RW	9Ch	Margin Payload
7	RsvdP	0	Reserved
6	RW	0	Usage Model
5:3	RW	7h	Margin Type
2:0	RW	0	Receiver Number

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[Table 111] Margining Lane Status Register (Lane 0)

Bits	Type	Default Value	Description
15:8	RO	0	MarginPayload Status
7	RsvdP	0	Reserved
6	RO	0	Usage Model Status
5:3	RO	0	Margin Type Status
2:0	RO	0	Receiver Number Status

[Table 112] Margining Lane Control Register (Lane 1)

Bits	Type	Default Value	Description
15:8	RW	9Ch	Margin Payload
7	RsvdP	0	Reserved
6	RW	0	Usage Model
5:3	RW	7h	Margin Type
2:0	RW	0	Receiver Number

[Table 113] Margining Lane Status Register (Lane 1)

Bits	Type	Default Value	Description
15:8	RO	0	MarginPayload Status
7	RsvdP	0	Reserved
6	RO	0	Usage Model Status
5:3	RO	0	Margin Type Status
2:0	RO	0	Receiver Number Status

[Table 114] Margining Lane Control Register (Lane 2)

Bits	Type	Default Value	Description
15:8	RW	9Ch	Margin Payload
7	RsvdP	0	Reserved
6	RW	0	Usage Model
5:3	RW	7h	Margin Type
2:0	RW	0	Receiver Number

[Table 115] Margining Lane Status Register (Lane 2)

Bits	Type	Default Value	Description
15:8	RO	0	MarginPayload Status
7	RsvdP	0	Reserved
6	RO	0	Usage Model Status
5:3	RO	0	Margin Type Status
2:0	RO	0	Receiver Number Status

[Table 116] Margining Lane Control Register (Lane 3)

Bits	Type	Default Value	Description
15:8	RW	9Ch	Margin Payload
7	RsvdP	0	Reserved
6	RW	0	Usage Model
5:3	RW	7h	Margin Type
2:0	RW	0	Receiver Number

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[Table 117] Margining Lane Status Register (Lane 3)

Bits	Type	Default Value	Description
15:8	RW	0	Margin Payload Status
7	RsvdP	0	Reserved
6	RW	0	Usage Model Status
5:3	RW	0	Margin Type Status
2:0	RW	0	Receiver Number Status

[Table 118] Margining Lane Control Register (Lane 4)

Bits	Type	Default Value	Description
15:8	RW	9Ch	Margin Payload
7	RsvdP	0	Reserved
6	RW	0	Usage Model
5:3	RW	7h	Margin Type
2:0	RW	0	Receiver Number

[Table 119] Margining Lane Status Register (Lane 4)

Bits	Type	Default Value	Description
15:8	RW	0	Margin Payload Status
7	RsvdP	0	Reserved
6	RW	0	Usage Model Status
5:3	RW	0	Margin Type Status
2:0	RW	0	Receiver Number Status

[Table 120] Margining Lane Control Register (Lane 5)

Bits	Type	Default Value	Description
15:8	RW	9Ch	Margin Payload
7	RsvdP	0	Reserved
6	RW	0	Usage Model
5:3	RW	7h	Margin Type
2:0	RW	0	Receiver Number

[Table 121] Margining Lane Status Register (Lane 5)

Bits	Type	Default Value	Description
15:8	RW	0	Margin Payload Status
7	RsvdP	0	Reserved
6	RW	0	Usage Model Status
5:3	RW	0	Margin Type Status
2:0	RW	0	Receiver Number Status

[Table 122] Margining Lane Control Register (Lane 6)

Bits	Spec Type	Default Value	Description
15:8	RW	9Ch	Margin Payload
7	RsvdP	0	Reserved
6	RW	0	Usage Model
5:3	RW	7h	Margin Type
2:0	RW	0	Receiver Number

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[Table 123] Margining Lane Status Register (Lane 6)

Bits	Spec Type	Default Value	Description
15:8	RO	0	MarginPayload Status
7	RsvdP	0	Reserved
6	RO	0	Usage Model Status
5:3	RO	0	Margin Type Status
2:0	RO	0	Receiver Number Status

[Table 124] Margining Lane Control Register (Lane 7)

Bits	Spec Type	Default Value	Description
15:8	RW	9Ch	Margin Payload
7	RsvdP	0	Reserved
6	RW	0	Usage Model
5:3	RW	7h	Margin Type
2:0	RW	0	Receiver Number

[Table 125] Margining Lane Status Register (Lane 7)

Bits	Spec Type	Default Value	Description
15:8	RO	0	Margin Payload Status
7	RsvdP	0	Reserved
6	RO	0	Usage Model Status
5:3	RO	0	Margin Type Status
2:0	RO	0	Receiver Number Status

### 5.1.4.7 Single Root I/O Virtualization (SR-IOV) Capability

[Table 126] SR-IOV Extended Capability Header Summary

Start Address	End Address	Symbol	Description
1E8h	1EBh		SR-IOV Extended Capability Header
1ECh	1EFh		SR-IOV Capabilities
1F0h	1F1h		SR-IOV Control
1F2h	1F3h		SR-IOV Status
1F4h	1F5h		InitialVFs
1F6h	1F7h		TotalVFs
1F8h	1F9h		NumVFs
1FAh	1FBh		Function Dependency Link
1FCh	1FDh		First VF Offset
1FEh	1FFh		VF Stride
200h	203h		VF Device ID
204h	207h		Supported Page Sizes
208h	20Bh		System Page Size
20Ch	20Fh		VF BAR0
210h	213h		VF BAR1
214h	217h		VF BAR2
218h	21Bh		VF BAR3
21Ch	21Fh		VF BAR4
220h	223h		VF BAR5
224h	227h		VF Migration State Array Offset

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[Table 127] SR-IOV Extended Capability Header

Bits	Type	Default Value	Description
31:20	RO	3A4h	Next Capability Pointer
19:16	RO	1h	Capability Version
15:0	RO	10h	PCI Express Extended Capability ID

[Table 128] SR-IOV Capabilities

Bits	Type	Default Value	Description
31:21	RO	0	VF Migration Interrupt Message Number
20:3	RsvdP	0	Reserved
2	HwInit	0	VF 10-Bit Tag Requester Supported
1	RO	1h	ARI Capable Hierarchy Preserved
0	RO	0	VF Migration Capable

[Table 129] SR-IOV Control

Bits	Type	Default Value	Description
15:6	RsvdP	0	Reserved
5	RW or RO	0	VF 10-Bit Tag Requester Enable
4	RW or RO	0	ARI Capable Hierarchy
3	RW	0	VF MSE
2	RW	0	VF Migration Interrupt Enable
1	RW or RO	0	VF Migration Enable
0	RW	0	VF Enable

[Table 130] SR-IOV Status

Bits	Type	Default Value	Description
15:1	RsvdZ	0	Reserved
0	RW1C	0	VF Migration Status

[Table 131] InitialVFs

Bits	Type	Default Value	Description
15:0	HwInit/RO	20h	InitialVFs

[Table 132] TotalVFs

Bits	Type	Default Value	Description
15:0	HwInit/RO	20h	TotalVFs

[Table 133] NumVFs

Bits	Type	Default Value	Description
15:0	RW	0	NumVFs

[Table 134] Function Dependency Link

Bits	Type	Default Value	Description
15:8		0	Reserved
7:0		0	Function Dependency Link

[Table 135] First VF Offset

Bits	Type	Default Value	Description
15:0	RO	2h	First VF Offset

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[Table 136] VF Stride

Bits	Type	Default Value	Description
15:0	RO	1h	VF Stride

[Table 137] VF Device ID

Bits	Type	Default Value	Description
31:16	RO	A825h	VF Device ID
15:0	RsvdP	0	Reserved

[Table 138] Supported Page Sizes

Bits	Type	Default Value	Description
31:0	RO	553h	Supported Page Sizes

[Table 139] System Page Size

Bits	Type	Default Value	Description
31:0	RW	1h	System Page Size

[Table 140] VF BAR0

Bits	Type	Default Value	Description
31:15		0	VF Base Address
14:4		0	Reserved
3		0	Pre-Fetchable
2:1		2h	Address Type (64-bit)
0	RO	0	Memory Space Indicator (MEMSI)

[Table 141] VF BAR1

Bits	Type	Default Value	Description
31:0		0	VF BAR1

[Table 142] VF BAR2

Bits	Type	Default Value	Description
31:0		0	N/A

[Table 143] VF BAR3

Bits	Type	Default Value	Description
31:0		0	N/A

[Table 144] VF BAR4

Bits	Type	Default Value	Description
31:0		0	N/A

[Table 145] VF BAR5

Bits	Type	Default Value	Description
31:0		0	N/A

[Table 146] VF Migration State Array Offset

Bits	Type	Default Value	Description
31:3		0	VF Migration State Offset
2:0		0	VF Migration State BIR

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### 5.1.4.8 Data Link Feature Extended Capability

[Table 147] Data Link Feature Extended Summary

Start Address	End Address	Symbol	Description
3A4h	3A7h		Data Link Feature Extended Capability Header
3A8h	3ABh		Data Link Feature Capabilities Register
3ACh	3AFh		Data Link Feature Status Register

[Table 148] Data Link Feature Extended Capability Header

Bits	Spec Type	Default Value	Description
31:20	RO	0h	Next Capability Offset
19:16	RO	1h	Capability Version
15:0	RO	25h	PCI Express Extended Capability ID

[Table 149] Data Link Feature Capabilities Register

Bits	Spec Type	Default Value	Description
31	HwInit	1h	Data Link Feature Exchange Enable
30:23	RsvdP	0h	Reserved
22:1	RsvdP	0h	Reserved
0	HwInit	1h	Local Scaled Flow Control Supported

[Table 150] Data Link Feature Status Register

Bits	Spec Type	Default Value	Description
31	RO	0h	Remote Data Link Feature Supported Valid
30:23	RsvdP	0h	Reserved
22:1	RO	0h	Undefined
0	RO	0h	Remote Scaled Flow Control Supported

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## 5.2 NVM Express Registers

### 5.2.1 Register Summary

[Table 151] Register Summary

Start Address	End Address	Name	Type
00h	07h	CAP	Controller Capabilities
08h	0Bh	VS	Version
0Ch	0Fh	INTMS	Interrupt Mask Set
10h	13h	INTMC	Interrupt Mask Clear
14h	17h	CC	Controller Configuration
18h	1Bh	Reserved	Reserved
1Ch	1Fh	CSTS	Controller Status
20h	23h	NSSR	NVM Subsystem Reset (Optional)
24h	27h	AQA	Admin Queue Attributes
28h	2Fh	ASQ	Admin Submission Queue Base Address
30h	37h	ACQ	Admin Completion Queue Base Address
38h	EFFh	Reserved	Reserved
F00h	FFFh	Reserved	Command Set Specific
1000h	1003h	SQ0TDBL	Submission Queue 0 Tail Doorbell (Admin)
1000h + (1 * (4 << CAP.DSTRD))	1003h + (1 * (4 << CAP.DSTRD))	CQ0TDBL	Completion Queue 0 Head Doorbell (Admin)
...			
1000h + (2y * (4 << CAP.DSTRD))	1003h + (2y * (4 << CAP.DSTRD))	SQyTDBL	Submission Queue y Tail Doorbell
1000h + ((2y + 1) * (4 << CAP.DSTRD))	1003h + ((2y + 1) * (4 << CAP.DSTRD))	CQyHDBL	Completion Queue y Head Doorbell

### 5.2.2 Controller Registers

[Table 152] Controller Capabilities

Bits	Type	Name	Default Value	Description
63:56	RO	-	0h	Reserved
55:52	RO	MPSMAX	01h	Memory Page Size Maximum ( $(2 ^ (12 + MPSMAX))$ ).
51:48	RO	MPSMIN	0	Memory Page Size Minimum ( $2 ^ (12 + MPSMIN)$ ).
47:45	RO	-	0	Reserved
44:37	RO	CSS	1h	Command Sets Supported 1h: NVM command set
36	RO	NSSRS	1h	NVM Subsystem Reset Supported (NSSRS)
35:32	RO	DSTRD	0	Doorbell Stride 0: Stride of 4 bytes
31:24	RO	TO	3Ch	Timeout (This field is in 500 millisecond units)
23:19	RO	-	0	Reserved
18:17	RO	AMS	1	Arbitration Mechanism Supported
16	RO	CQR	1	Contiguous Queues Required
15:0	RO	MQES	3FFh	Maximum Queue Entries Supported
Offset 20h, 31:00	RW	NSSRC	0h	NVM Subsystem Reset Control (NSSRC)

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[Table 153] Version

Bits	Type	Name	Default Value	Description
31:16	RO	MJR	1h	Major Version Number
15:8	RO	MNR	3h	Minor Version Number
7:0	RO	TER	0h	Tertiary Version Number

**NOTE:**

The PM1733a supports NVM Express version 1.3

[Table 154] Interrupt Mask Set

Bits	Type	Name	Default Value	Description
31:00	RW1S	IVMS	0	Interrupt Vector Mask Set

[Table 155] Interrupt Mask Clear

Bits	Type	Name	Default Value	Description
31:00	RW1C	IVMC	0	Interrupt Vector Mask Clear

[Table 156] Controller Configuration

Bits	Type	Name	Default Value	Description
31:24	RO	-	0	Reserved
23:20	RW	IOCQES	0	I/O Completion Queue Entry Size (Configured as a power of 2) (Should be set to 4 for a 16 byte entry size)
19:16	RW	IOSQES	0	I/O Submission Queue Entry Size (Configured as a power of 2) (Should be set to 6 for a 64 byte entry size)
15:14	RW	SHN	0	Shutdown Notification 0h: No notification 1h: Normal shutdown notification 2h: Abrupt shutdown notification 3h: Reserved CSTS.SHST indicates shutdown status.
13:11	RW	AMS	0	Arbitration Mechanism Selected 0h: Round Robin No other values supported.
10:7	RW	MPS	0	Memory Page Size MPS is $2^{(12+MPS)}$ Shall be within CAP.MPSMAX and CAP.MPSMIN ranges.
6:4	RW	CSS	0	Command Set Selected 0h: NVM Command Set No other values supported
3:1	RO	-	0	Reserved
0	RW	EN	0	Enable When set to 1, controller shall process commands. When cleared to 0, controller shall not process commands. This field is subject to CSTS.RDY and CAP.TO restrictions.

[Table 157] Controller Status

Bits	Type	Name	Default Value	Description
31:4	RO	-	0	Reserved
3:2	RO	SHST	0	Shutdown Status 0h: Normal operation, no shutdown requested 1h: Shutdown processing occurring 2h: Shutdown processing complete 3h: Reserved
1	RO	CFS	0	Controller Fatal Status
0	RO	RDY	0	1h: Controller ready to process commands 0h: Controller shall not process commands.

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[Table 158] Admin Queue Attributes

Bits	Type	Name	Default Value	Description
31:28	RO	-	0	Reserved
27:16	RW	ACQS	0	Admin Completion Queue Size Max: 4096 (Value of 4095h - 0's based value)
15:12	RO	-	0	Reserved
11:0	RW	ASQS	0	Admin Submission Queue Size Max: 4096 (Value of 4095h - 0's based value)

[Table 159] Admin Submission Queue Base Address

Bits	Type	Name	Default Value	Description
63:12	RW	ASQB	0	Admin Submission Queue Base Address
11:0	RO	-	0	Reserved

[Table 160] Admin Completion Queue Base Address

Bits	Type	Name	Default Value	Description
63:12	RW	ACQB	0	Admin Completion Queue Base Address
11:0	RO	-	0	Reserved

[Table 161] Submission Queue Tail y Doorbell

Bits	Type	Name	Default Value	Description
31:16	RO	-	0	Reserved
15:0	RW	SQT	0	Submission Queue Tail

[Table 162] Completion Queue Head y Doorbell

Bits	Type	Name	Default Value	Description
31:16	RO	-	0	Reserved
15:0	RW	CQH	0	Completion Queue Head

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## 6.0 SUPPORTED COMMAND SET

### 6.1 Admin Command Set

[Table 163] Opcode for Admin Commands

Opcode (Hex)	Command Name
00h	Delete I/O Submission Queue
01h	Create I/O Submission Queue
02h	Get Log Page - Error Information (01h) - SMART/Health Information (02h) - Firmware Slot Information (03h, M)
04h	Delete I/O Completion Queue
05h	Create I/O Completion Queue
06h	Identify
08h	Abort
09h	Set Feature - Arbitration (01h) - Power Management (02h) - LBA Range Type (03h) - Temperature Threshold (04h) - Error Recovery (05h) - Number of Queues (07h) - Interrupt Coalescing (08h) - Interrupt Vector Configuration (09h) - Write Atomicity (0Ah) - Asynchronous Event Configuration (0Bh) - Software Progress Marker (80h)
0Ah	Get Feature - Arbitration (01h) - LBA Range Type (03h) - Temperature Threshold (04h) - Error Recovery (05h) - Number of Queues (07h) - Interrupt Coalescing (08h) - Interrupt Vector Configuration (09h) - Write Atomicity (0Ah) - Asynchronous Event Configuration (0Bh) - Software Progress Marker (80h)
0Ch	Asynchronous Event Request
0Dh	Namespace Management
10h	Firmware Commit
11h	Firmware Image Download
14h	Device Self-test
15h	Namespace Attachment
80h	Format NVM
81h - BFh	I/O Command Set Specific

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## 6.1.1 Identify Command

The Identify Command returns the data described below.

[Table 164] Identify Controller Data Structure

Bytes	O/M	Default Value	Description
1:0	M	144Dh	PCI Vendor ID
3:2	M	144Dh	PCI Subsystem Vendor ID
23:4	M	SXXXNXXXXXXXXX	Serial Number (ASCII), X: Variables
63:24	M	1.92TB: MZWLR1T9HCJR-00A07 3.84TB: MZWLR3T8HCLS-00A07 7.68TB: MZWLR7T6HBLA-00A07 15.36TB: MZWLR15THBLA-00A07 30.72TB: MZWLR30THBLA-00A07	Model Number (ASCII)
71:64	M	XXXXXXXXQ	Firmware Revision, X: Variables
72	M	3h	Recommended Arbitration Burst
75:73	M	002538h	IEEE OUI Byte 73 - 38h Byte 74 - 25h Byte 75 - 0h
76	O	3h	Controller Multi-Path I/O and Namespace Sharing Capabilities (CMIC)
77	M	5h	Maximum Data Transfer Size(MDTS)
79:78	M	41h	Controller ID (CNTLID)
83:80	M	10300h	Version (VER)
87:84	M	E4E1C0h (1.92TB,3.84TB,7.68TB) 1C9C380h (15.36TB,30.72TB)	RTD3 Resume Latency (RTD3R)
91:88	M	989680h (1.92TB,3.84TB,7.68TB) 243D580h (15.36TB,30.72TB)	RTD3 Entry Latency (RTD3E)
95:92	M	300h	Optional Asynchronous Event Supported (OAES)
99:96	M	0h	Controller Attributes (CTRATT)
239:100		-	Reserved
255:240			Refer to the NVMe Management Interface Specification for definition.
257:256	M	DFh	Optional Admin Command Support
258	M	7Fh	Abort Command Limit (Maximum number of concurrently outstanding Abort commands) (0's based value)
259	M	Fh	Asynchronous Event Request Limit (Maximum number of concurrently outstanding Asynchronous Event Request commands) (0's based value)
260	M	17h	Firmware Updates
261	M	Eh	Log Page Attributes
262	M	FFh	Error Log Page Entries (Number of Error Information log entries stored by controller) (0's based value)
263	M	0h	Number of Power States Support (0's based value)
264	M	1h	Admin Vendor Specific Command Configuration
265	O	0h	Autonomous Power State Transition Attributes (APSTA)
267:266	M	159h (72°C) - 1.92TB,3.84TB,7.68TB 157h (70°C) - 15.36TB, 30.72TB	Warning Composite Temperature Threshold (WCTEMP)
269:268	M	168h (87°C) - 1.92TB,3.84TB,7.68TB 163h (82°C) - 15.36TB, 30.72TB	Critical Composite Temperature Threshold (CCTEMP)
271:270	O	82h	Maximum Time for Firmware Activation (MTFA)
275:272	O	0h	Host Memory Buffer Preferred Size (HMPRE):
279:276	O	0h	Host Memory Buffer Minimum Size (HMMIN):

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295:280	O	1.92TB : 1BF1FC56000h 3.84TB : 37E3EE56000h 7.68TB : 6FC7D256000h 15.36TB : DF880000000h 30.72TB : 1BF0C0000000h	Total NVM Capacity (TNVMCAP):
311:296	O	0h	Unallocated NVM Capacity (UNVMCAP):
315:312	O	0h	Replay Protected Memory Block Support (RPMBS):
317:316	O	2h	Extended Device Self-test Time (EDSTT)
318	O	1h	Device Self-test Options (DSTO)
319	M	FFh	Firmware Update Granularity (FWUG)
321:320	M	0h	Keep Alive Support(KAS)
327:322	-	0h	Reserved
331:328	O	3h	Sanitize Capabilities (SANICAP)
511:332	-	-	Reserved
512	M	66h	Submission Queue Entry Size
513	M	44h	Completion Queue Entry Size
515:514	M	0h	Maximum Outstanding Commands
519:516	M	20h	Number of Namespaces
521:520	M	7Fh	Optional NVM Command Support
523:522	M	0h	Fused Operation Support
524	M	4h	Format NVM Attributes
525	M	0h	Volatile Write Cache
527:526	M	0h	Atomic Write Unit Normal All commands atomic
529:528	M	0h	Atomic Write Unit Power Fail (0's based value)
530	M	1h	NVM Vendor Specific Command Configuration
531	M	-	Reserved
533:532	O	0h	Atomic Compare & Write Unit (ACWU)
535:534	M	-	Reserved
539:536	O	F0002h	SGL Support (SGLS)
767:540	M	-	Reserved
1023:768	M	nqn.1994-11.com.samsung:nvme: PM1733a:2.5-inch: SXXXNXXXXXXXXX	NVM Subsystem NVMe Qualified Name(SUBNQN)
I/O Command Set Attributes			
2047:1024	-	-	Reserved
Power State Descriptors			
2079:2048	M	-	Power State 0 Descriptor
2111:2080	O	-	Power State 1 Descriptor
2143:2112	O		Power State 2 Descriptor
2175:2144	O		Power State 3 Descriptor
2207:2176	O		Power State 4 Descriptor
...	-		
3071:3040	O	-	Power State 31 Descriptor (N/A)
4095:3072	-	0h	Samsung Reserved

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[Table 165] Identify Power State Descriptor Data Structure

Bits	Power State 0	Description
255:184	0	Reserved
183:182	2h	Active Power Scale(APS)
181:179	0	Reserved
178:176	2h	Active Power Workload(APW)
175:160	866h	Active Power(ACTP)
159:152	0	Reserved
151:150	2h	Idle Power Scale(IPS)
149:144	0	Reserved
143:128	1F4h	Idle Power(IDLP)
127:125	0	Reserved
124:120	0h	Relative Write Latency
119:117	0	Reserved
116:112	0h	Relative Write Throughput
111:109	0	Reserved
108:104	0h	Relative Read Latency
103:101	0	Reserved
100:96	0h	Relative Read Throughput
95:64	0h	Exit Latency (100us)
63:32	0h	Entry Latency (100us)
31:26	0	Reserved
25	0h	Non-Operational State(NOPS)
24	0h	Max Power Scale(MXPS)
23:16	0	Reserved
15:00	9C4h	Maximum Power

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[Table 166] Identify Namespace Data Structure

Bytes	O/M	Default Value	Description
7:0	M	1.92TB : FD8FE2B0h 3.84TB : 1BF1F72B0h 7.68TB : 37E3E92B0h 15.36TB : 6FC400000h 30.72TB : DF8600000h	Namespace Size
15:8	M	1.92TB : FD8FE2B0h 3.84TB : 1BF1F72B0h 7.68TB : 37E3E92B0h 15.36TB : 6FC400000h 30.72TB : DF8600000h	Namespace Capacity
23:16	M	1.92TB : FD8FE2B0h 3.84TB : 1BF1F72B0h 7.68TB : 37E3E92B0h 15.36TB : 6FC400000h 30.72TB : DF8600000h	Namespace Utilization
24	M	0h	Namespace Features Bits 7:1 Reserved Bit 0: Thin provisioning not supported
25	M	4h	Number of LBA Formats
26	M	10h	Formatted LBA Size Bits 7:5 – Reserved Bit 4: Metadata interleaved or separate (based on LBA format) Bit 3:0 – Indicates LBA format
27	M	3h	Metadata Capabilities Bits 7:2 – Reserved Bit 1 – Supports Metadata as separate buffer Bit 0 – Supports Metadata as extended LBA
28	M	1Fh	End-to-end Data Protection Capabilities Bits 7:5 – Reserved Bit 4 – Supports protection information as last 8 bytes of Metadata Bit 3 – Supports protection information as first 8 bytes of Metadata Bit 2 – Supports Type 3 protection information Bit 1 – Supports Type 2 protection information Bit 0 – Supports Type 1 protection information
29	M	0h	End-to-End Data Protection Type Settings Bits 7:4 – Reserved Bit 3 – 1: Protection information transferred as first 8 bytes of Metadata Bit 3 – 0: Protection information transferred as last 8 bytes of Metadata Bit 2:0 – 000b: Protection information disabled Bit 2:0 – 1h: Protection type 1 enabled Bit 2:0 – 2h: Protection type 2 enabled Bit 2:0 – 3h: Protection type 3 enabled
30	O	1h	Namespace Multi-path I/O and Namespace Sharing Capabilities (NMIC):
31	O	FFh	Reservation Capabilities (RESCAP):
32	O	80h	Format Progress Indicator (FPI)
33	O	1h	Deallocate Logical Block Features (DLFEAT):
35:34	O	0h	Namespace Atomic Write Unit Normal (NAWUN)
37:36	O	0h	Namespace Atomic Write Unit Power Fail (NAWUPF)
39:38	O	0h	Namespace Atomic Compare & Write Unit (NACWU)
41:40	O	0h	Namespace Atomic Boundary Size Normal (NABSN)
43:42	O	0h	Namespace Atomic Boundary Offset (NABO)
45:44	O	0h	Namespace Atomic Boundary Size Power Fail (NABSPF)
47:46	-	-	Reserved
63:48		1.92TB : 1BF1FC56000h 3.84TB : 37E3EE56000h 7.68TB : 6FC7D256000h 15.36TB : DF880000000h 30.72TB : 1BF0C000000h	NVM Capacity (NVMCAP)
103:64	-	-	Reserved

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119:104	O	Device Dependant	Namespace Globally Unique Identifier (NGUID)
127:120	O	0h	IEEE Extended Unique Identifier(EUI64)
131:128	M	1090000h	LBA Format 0 Support
135:132	O	3090008h	LBA Format 1 Support
139:136	O	C0000h	LBA Format 2 Support
143:140	O	20C0008h	LBA Format 3 Support
147:144	O	30C0040h	LBA Format 4 Support
191:188	O	-	LBA Format 15 Support (N/A)
383:192	-	-	Reserved
Vendor Specific			
4095:384	-	-	Samsung Reserved

[Table 167] LBA Format 0 Data Structure

Bits	Name	Default Value	Description
31:26		0h	Reserved
25:24	RP	1h	Relative Performance
23:16	LBADS	9h	LBA Data Size
15:00	MS	0h	Metadata Size

[Table 168] LBA Format 1 Data Structure

Bits	Name	Default Value	Description
31:26		0h	Reserved
25:24	RP	3h	Relative Performance
23:16	LBADS	9h	LBA Data Size
15:00	MS	8h	Metadata Size

[Table 169] LBA Format 2 Data Structure

Bits	Name	Default Value	Description
31:26		0	Reserved
25:24	RP	0h	Relative Performance
23:16	LBADS	Ch	LBA Data Size
15:00	MS	0h	Metadata Size

[Table 170] LBA Format 3 Data Structure

Bits	Name	Default Value	Description
31:26		0	Reserved
25:24	RP	2h	Relative Performance
23:16	LBADS	Ch	LBA Data Size ( $2^n$ bytes)
15:00	MS	8h	Metadata Size (bytes)

[Table 171] LBA Format 4 Data Structure

Bits	Name	Default Value	Description
31:26		0	Reserved
25:24	RP	3h	Relative Performance
23:16	LBADS	Ch	LBA Data Size ( $2^n$ bytes)
15:00	MS	40h	Metadata Size (bytes)

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## 6.2 NVM Express I/O Command Set

[Table 172] Opcode for NVM Express I/O Commands

Opcode (Hex)	Command Name
00h	Flush
01h	Write
02h	Read
04h	Write Uncorrectable
05h	Write Zeroes
09h	Dataset Management
0Dh	Reservation Register
0Eh	Reservation Report
11h	Reservation Acquire
15h	Reservation Release

**NOTE:**

1) Deallocate feature in Dataset Management command is only supported in the Samsung SSD PM1733a.

### 6.2.1 SMART/Health Information

[Table 173] SMART/Health Information Log

Bytes	Default Value	Attribute Description
0	0	Critical Warning Bit 7:5 – Reserved Bit 4 – 1h: the volatile memory backup device has failed. (only valid if the controller has a volatile memory backup solution) Bit 3 – 1h: the media has been placed in read only mode Bit 2 – 1h: the NVM subsystem reliability has been degraded due to significant media related errors or any internal error that degrades NVM subsystem reliability Bit 1 – 1h: a temperature is above an over temperature threshold or below an under temperature threshold Bit 0 – 1h: the available spare space has fallen below the threshold
2:1	current temp.	Temperature
3	100	Available Spare
4	10	Available Spare Threshold
5	0	Percentage Used
31:6	-	Reserved
47:32	0	Data Units Read
63:48	0	Data Units Written
79:64	0	Host Read Commands
95:80	0	Host Write Commands
111:96	0	Controller Busy Time
127:112	0	Power Cycles
143:128	0	Power On Hours
159:144	0	Unsafe Shutdowns
175:160	0	Media and Data Integrity Errors
191:176	0	Number of Error Information Log Entries
195:192	0	Warning Composite Temperature Time
199:196	0	Critical Composite Temperature Time
201:200	current temp.	Temperature Sensor 1
203:202	Not support	Temperature Sensor 2
205:204	Not support	Temperature Sensor 3
207:206	Not support	Temperature Sensor 4
209:208	Not support	Temperature Sensor 5
211:210	Not support	Temperature Sensor 6

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213:212	Not support	Temperature Sensor 7
215:213	Not support	Temperature Sensor 8
219:216	Not support	Thermal Management Temperature 1 Transition Count
223:220	Not support	Thermal Management Temperature 2 Transition Count
227:224	Not support	Total Time For Thermal Management Temperature 1
231:228	Not support	Total Time For Thermal Management Temperature 2
511:232	-	Reserved

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## 7.0 SFF-8639 SMBus RESOURCES

This section listed data structures and registers accessible through SMBus interface.

Vital Product Data (VPD) is stored in SM-Bus slave address of 0xA6 (bits 7-1 correspond to 1010\_011x on the SM-Bus). H/W Temperature sensor SM-Bus slave address is 0x36 (bits 7-1 correspond to 0011\_011x). The legacy f/w simulated temperature sensor is located at SMBus slave address 0x38 (bits 7-1 correspond to 0011\_100x). The MI-Basic is accessible at 0xD4 (bits 7-1 correspond to 1101\_010x).

### 7.1 Vital Product Data (VPD) Structure

VPD listed device specific information for Enterprise PCIe SSD discovery and power allocation.

\*Data offset of VPD EEPROM is 1Byte(8bit).

Currently, VPD is provided following SFF U.2 format as following

bytes	Name	Value
0:2	Class Code	0x010802
3:4	Vendor ID	0x144D
5:24	Serial Number	Vendor Unique
25:64	Model Number	Vendor Unique
65	PCIe Port 0 Capabilities	0x04
66	PCIe Port 0 Capabilities	0x04
67	PCIe Port 1 Capabilities	0x04
68	PCIe Port 1 Capabilities	0x04
69:71	Initial Power Requirements	0x08
72:74	Max power Requirement	0x16
75	Cap List Pointer	0x50
76:79	Reserved	-
80:81	Temperature Sensor Cap ID	0x00A2
82:83	Next Cap Offset	0x0070
84	Sensor Type	0x00
85	Sensor Address	0x36
86:87	Reserved	0x0000
88:89	Warning Threshold	2/4/8TB: 0x048 16/32TB: 0x046
90:91	Overtemp Threshold	2/4/8TB: 0x057 16/32TB: 0x052
92:111	Reserved	0xFF
112:113	Dual Port Cap ID	0x00A0
114:115	Next Cap Offset	0x0074
116:117	Extended Dual Port Cap	0x00A3
118:119	Next Cap Offset	0x0000
120	Dual Port Vector	0x03
121:123	Reserved	0x0
124:255	Reserved	0xFF

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## 7.2 Temperature Sensor Register Summary

Offset	Type	Name	Description	Default
00	RO	Capabilities	Indicates the functions and capabilities	00EFh
01	RW	Configuration	Temperature sensor control	0000h
02	RW	High Limit	Temperature High Limit	0000h
03	RW	Low Limit	Temperature Low Limit	0000h
04	RW	TCRIT Limit	Critical Temperature	0000h
05	RO	Ambient Temp	Current Ambient Temperature	N/A
06	RO	Manufacture ID	PCI-SIG Manufacture ID	1C85h
07	RO	Device/Revision	Device ID and Revision number	2221h
08	RW	Resolution register	Sets temperature resolution	0001h

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## 8.0 PRODUCT COMPLIANCE

### 8.1 Product Regulatory Compliance and Certifications

Category	Certifications
Safety	cUL
	CE
	TUV-GS
	CB
EMC	CE (EU)
	BSMI (Taiwan)
	KC (South Korea)
	VCCI (Japan)
	RCM (Australia)
	FCC (USA) / IC (Canada)

The three existing compliance marks (C-Tick, A-Tick, and RCM) are consolidated into a single compliance mark - the RCM.



Caution: Any changes or modifications in construction of this device which are not expressly approved by the party responsible for compliance could void the user's authority to operate the equipment.

**NOTE:**

This equipment has been tested and found to comply with the limits for a Class B digital device, pursuant to part 15 of the FCC Rules. These limits are designed to provide reasonable protection against harmful interference in a residential installation. This equipment generates, uses and can radiate radio frequency energy and, if not installed and used in accordance with the instructions, may cause harmful interference to radio communications. However, there is no guarantee that interference will not occur in a particular installation. If this equipment does cause harmful interference to radio or television reception, which can be determined by turning the equipment off and on, the user is encouraged to try to correct the interference by one or more of the following measures:

- Reorient or relocate the receiving antenna.
- Increase the separation between the equipment and receiver.
- Connect the equipment into an outlet on a circuit different from that to which the receiver is connected.
- Consult the dealer or an experienced radio / TV technician for help.

Modifications not expressly approved by the manufacturer could void the user's authority to operate the equipment under FCC rules.



1. 기자재 명칭 : SSD (Solid State Drive)
2. 모델명(Model): 라벨 별도 표기
3. 제조연월 : 라벨 별도 표기
4. 제조자 : 삼성전자(주)
5. 제조국가 : 대한민국
6. 상호명 : 삼성전자(주)

Industry Canada ICES-003 Compliance Label:  
 CAN ICES-3 (B)/NMB-3(B)

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## 9.0 REFERENCES

[Table 174] Standards References

Item	Website
PCI Express Base Specification Revision 4.0	<a href="http://www.pcisig.com/specifications/">http://www.pcisig.com/specifications/</a>
NVM Express Specification Rev. 1.3	<a href="http://www.nvme.org/">http://www.nvme.org/</a>
NVMe Management Interface 1.0a	<a href="http://www.nvme.org/">http://www.nvme.org/</a>
Enterprise SSD Form Factor Version 1.0a	<a href="http://www.ssdformfactor.org/">http://www.ssdformfactor.org/</a>
Solid-State Drive Requirements and Endurance Test Method (JESD218B)	<a href="https://www.jedec.org/standards-documents/docs/jesd218B01">https://www.jedec.org/standards-documents/docs/jesd218B01</a>
Solid-State Drive Requirements and Endurance Test Method (JESD219A)	<a href="http://www.jedec.org/standards-documents/docs/jesd219a">http://www.jedec.org/standards-documents/docs/jesd219a</a>

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